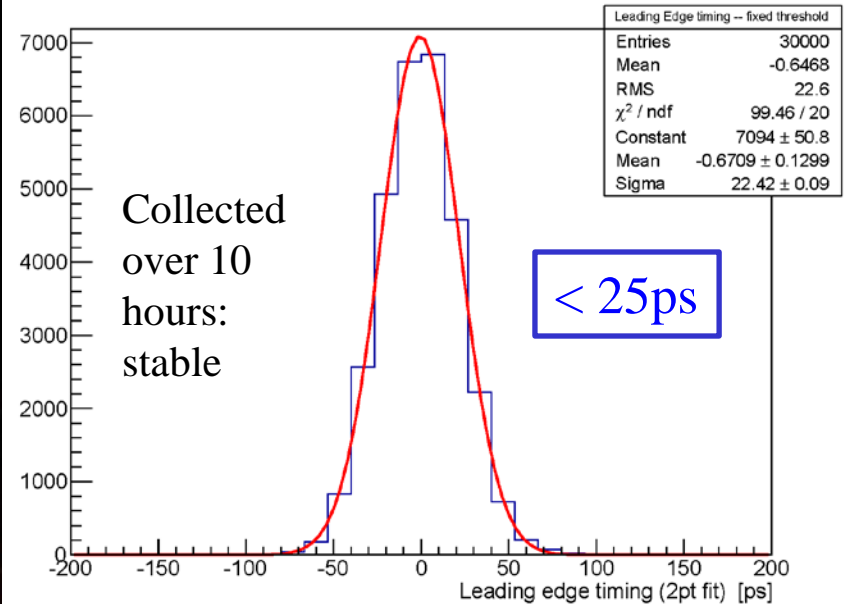


Understanding IRS3B, board-stack and mTC operation/calibration



IRS3B on eval board, Timing via on-board Cal pulser



Gary S. Varner
10 JUL 2014

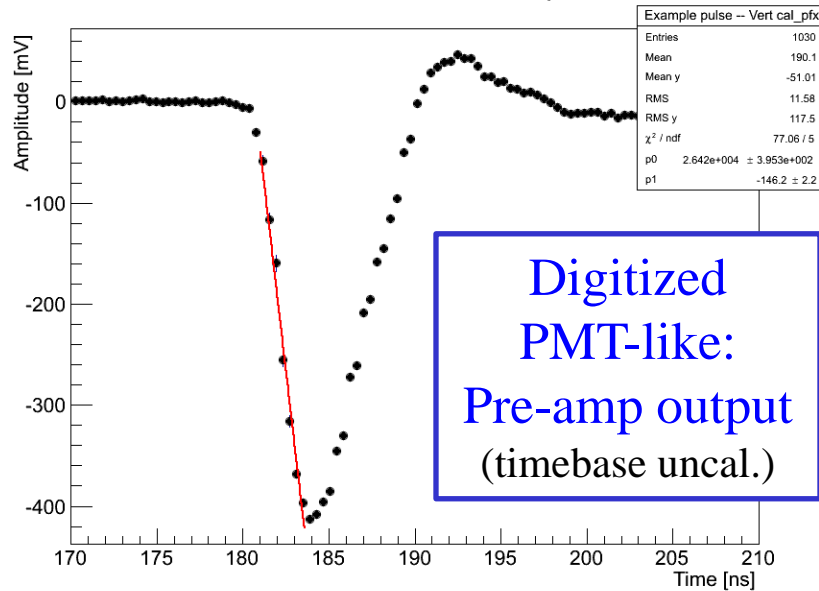
mTC Training Session #5

Roadmap

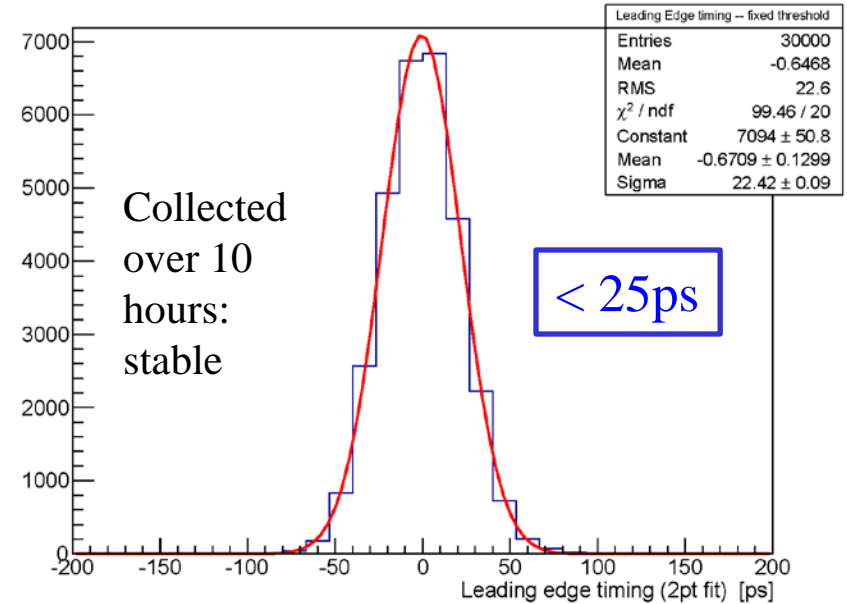
- mTC Readout
 - Currently at about Phase 1.5
 - You can get us to Phase 2.5
- Specifically
 - Operators need to understand Hardware/Firmware/Software
 - Develop real-time Data Quality Monitoring
- What I hope to convey:
 1. Details of the hardware: ASIC + boardstack
 2. Firmware and Configuration/Operating parameters
 3. Understand how to read and comprehend documentation and ask meaningful questions (“it doesn’t work” notably not amongst them)

Reminder: IRS3B not so bad

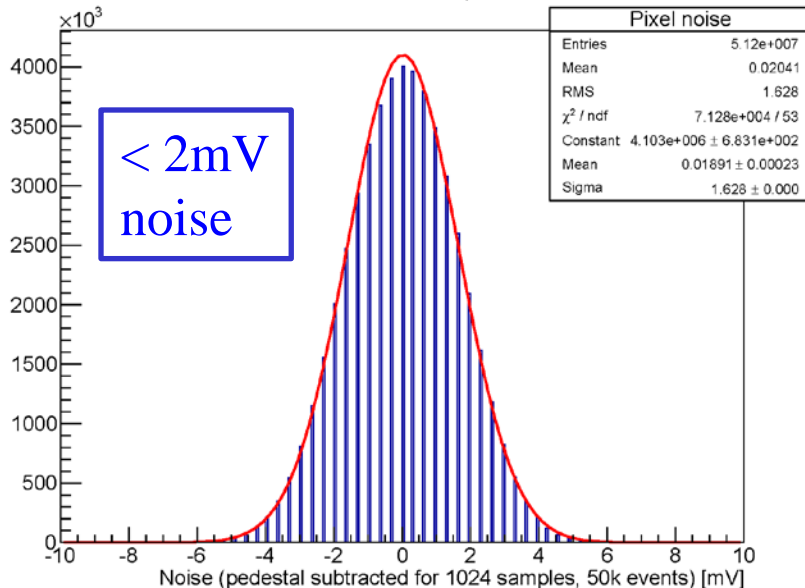
IRS3B on eval board, Cal pulser



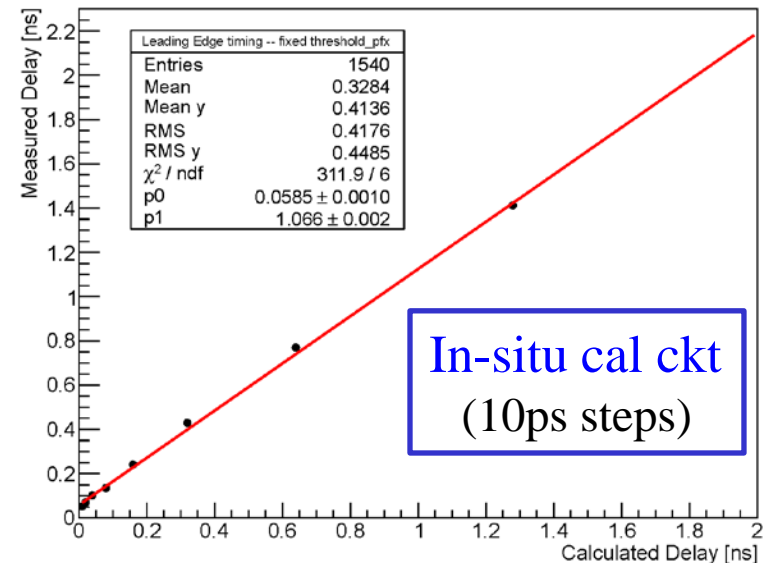
IRS3B on eval board, Timing via on-board Cal pulser



IRS3B on eval board, with bias2

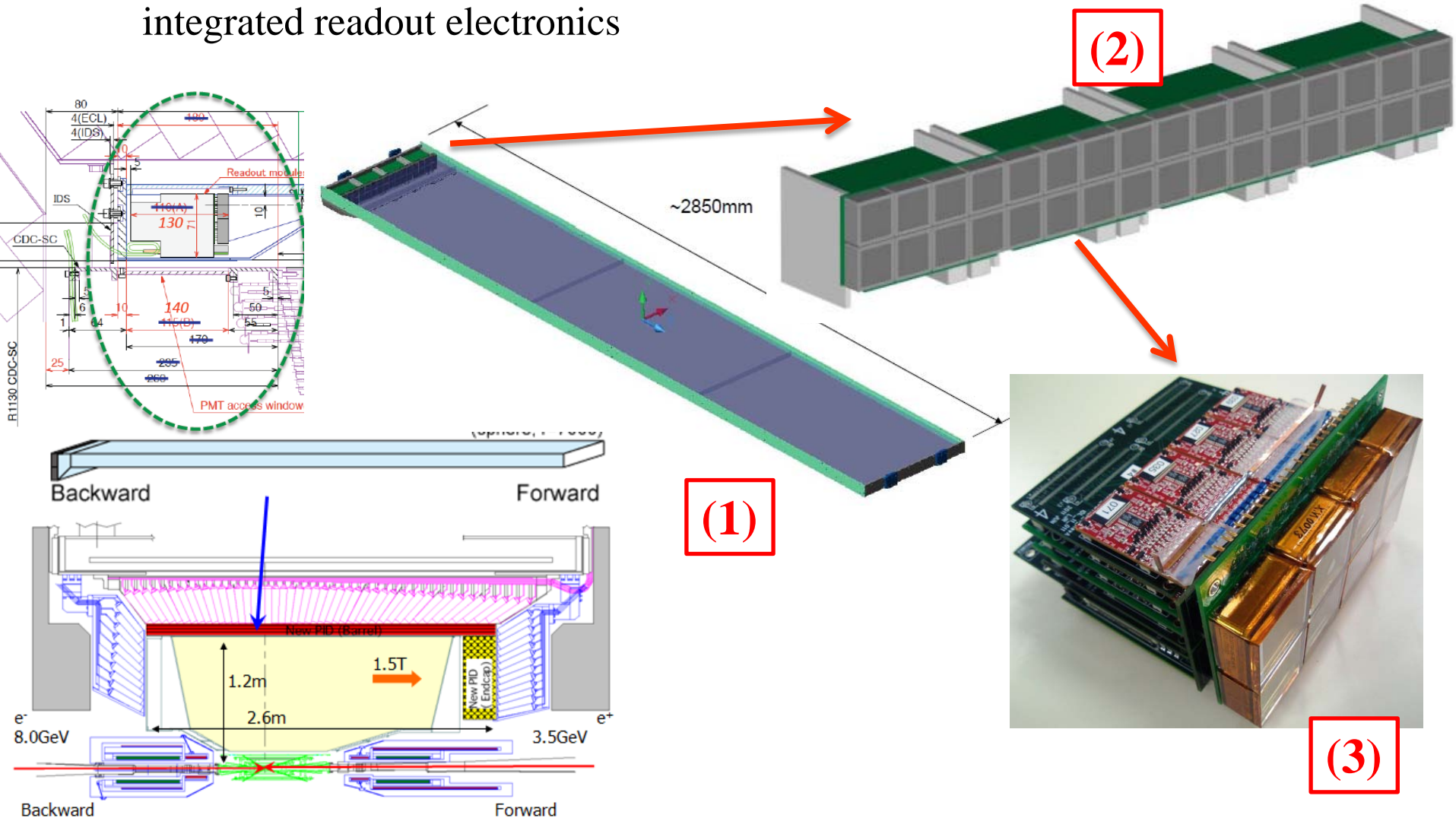


IRS3B on eval board, Cal pulser delay scan

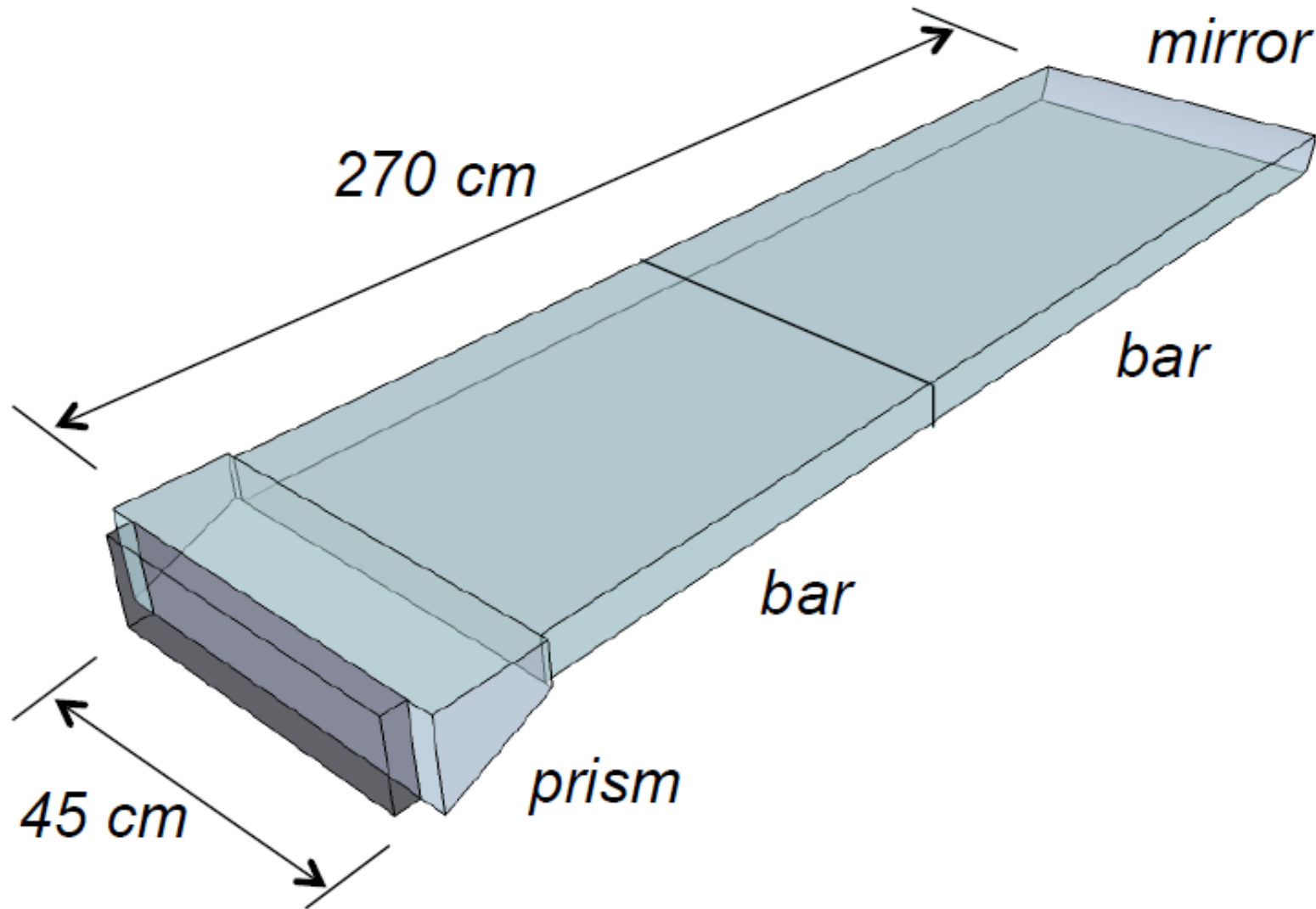


Belle II iTOP Counter

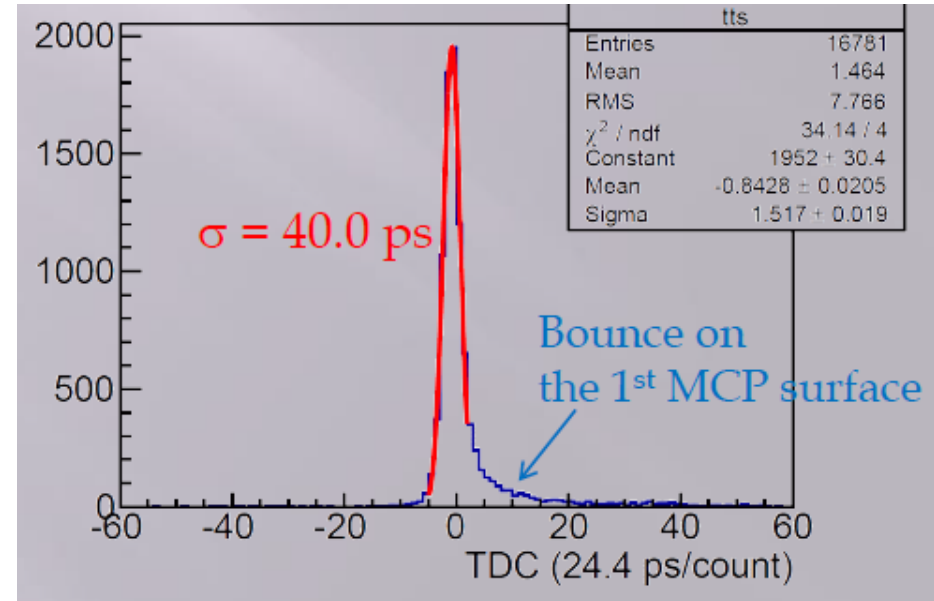
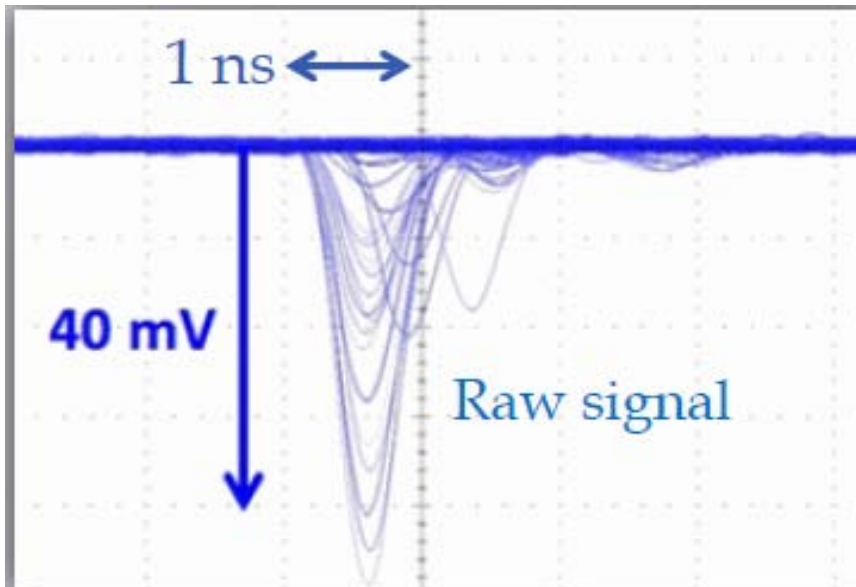
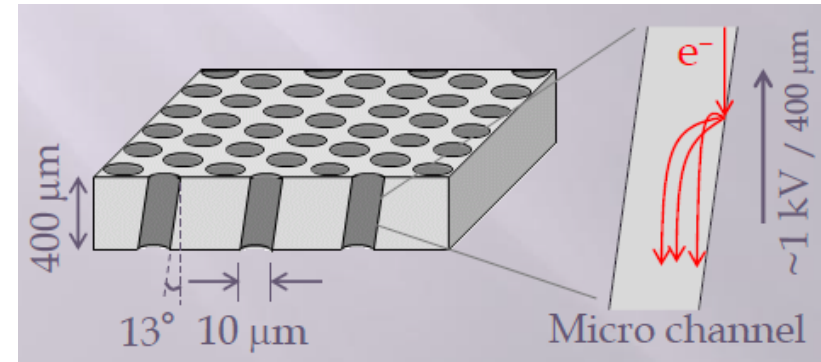
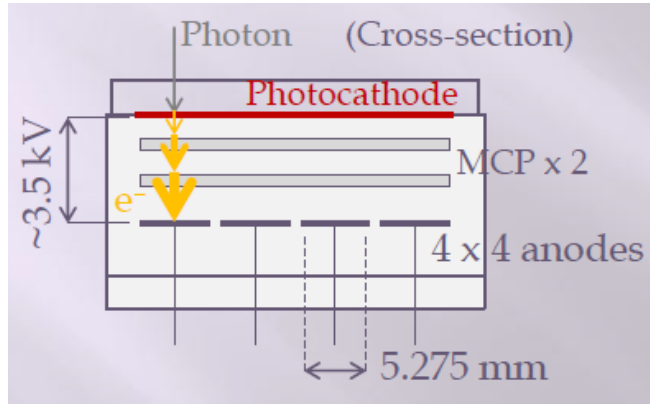
- 3 key elements: quartz radiator, micro-channel plate PMT array, integrated readout electronics



1) Quartz Radiator, Optics, Coupling



2) Micro-Channel Plate PMT (HPK SL-10)

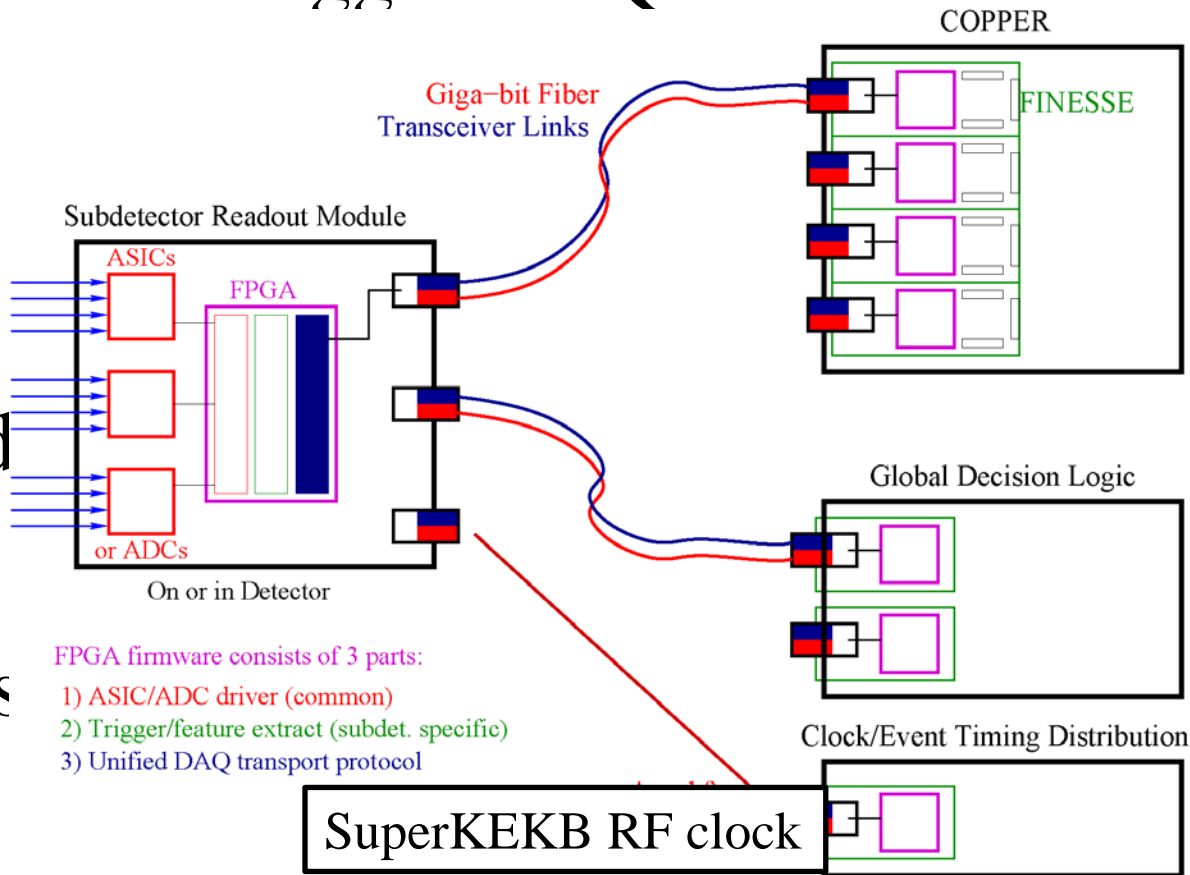


Works in 1.5T B-field

Peak Q.E. ~28% (24% min)

3) Integrated Readout Electronics

- Operate within Belle-II Trigger/DAQ environment
- $\geq 30\text{kHz}$ L1 trig
- Gbps fiber Tx/Rx
- COPPER backend
- Timing trigger
- iTOP: 8k channels
- 16 iTOP modules
- 4x 128-channel SRM/iTOP module (64x total)



SPring-8 2013 Run Schedule

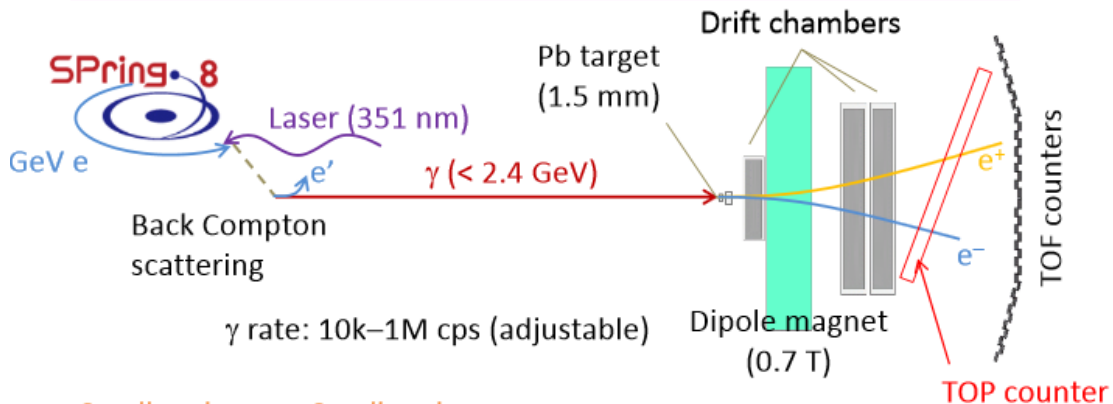
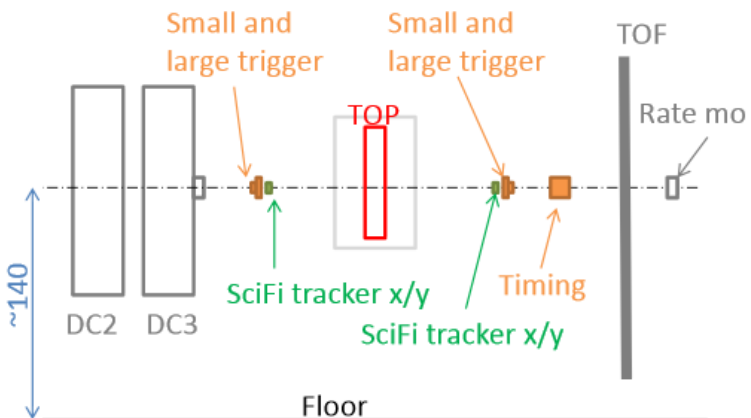
| June | | | | | | |
|------|-----|-----|-----|-----|-----|-----|
| Mon | Tue | Wed | Thu | Fri | Sat | Sun |
| | | | | | 1 | 2 |
| | | | | | 3 | |
| 3 | 4 | 5 | 6 | 7 | 8 | 9 |
| 4 | 5 | 6 | 7 | 8 | 9 | 10 |
| 10 | 11 | 12 | 13 | 14 | 15 | 16 |
| 11 | 12 | 13 | 14 | 15 | 16 | 17 |
| 17 | 18 | 19 | 20 | 21 | 22 | 23 |
| 18 | 19 | 20 | 21 | 22 | 23 | 24 |
| 24 | 25 | 26 | 27 | 28 | 29 | 30 |
| 25 | 26 | 27 | 28 | 29 | 30 | |

Beam test w/ LEPS detector: Full detector (final optics)



IRS3B Readout
“Vertical slice” DAQ
(FTSW+FINESSE/COPPER)

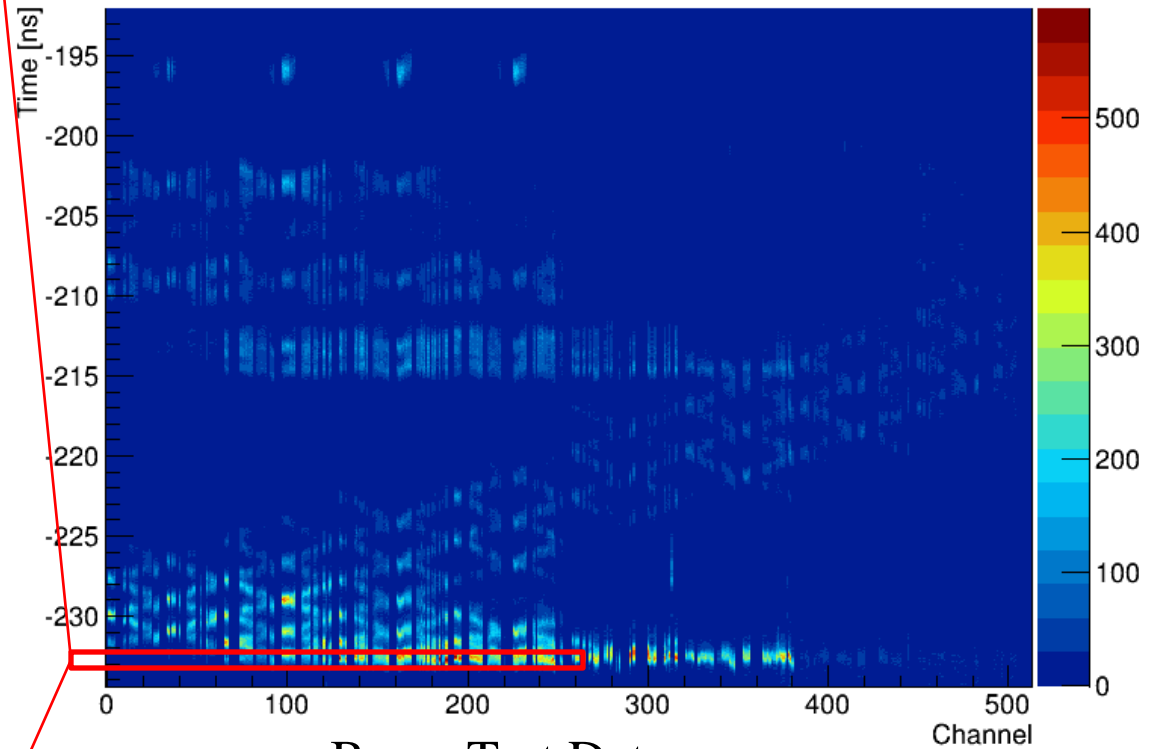
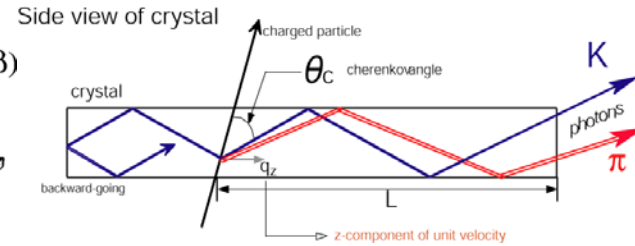
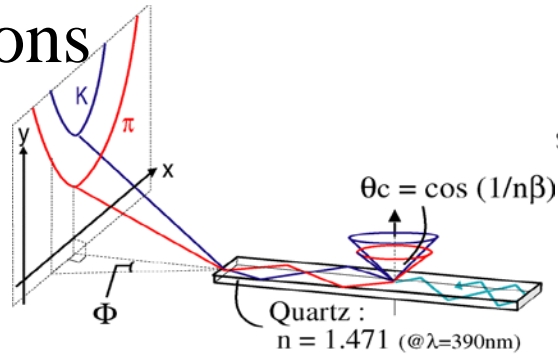
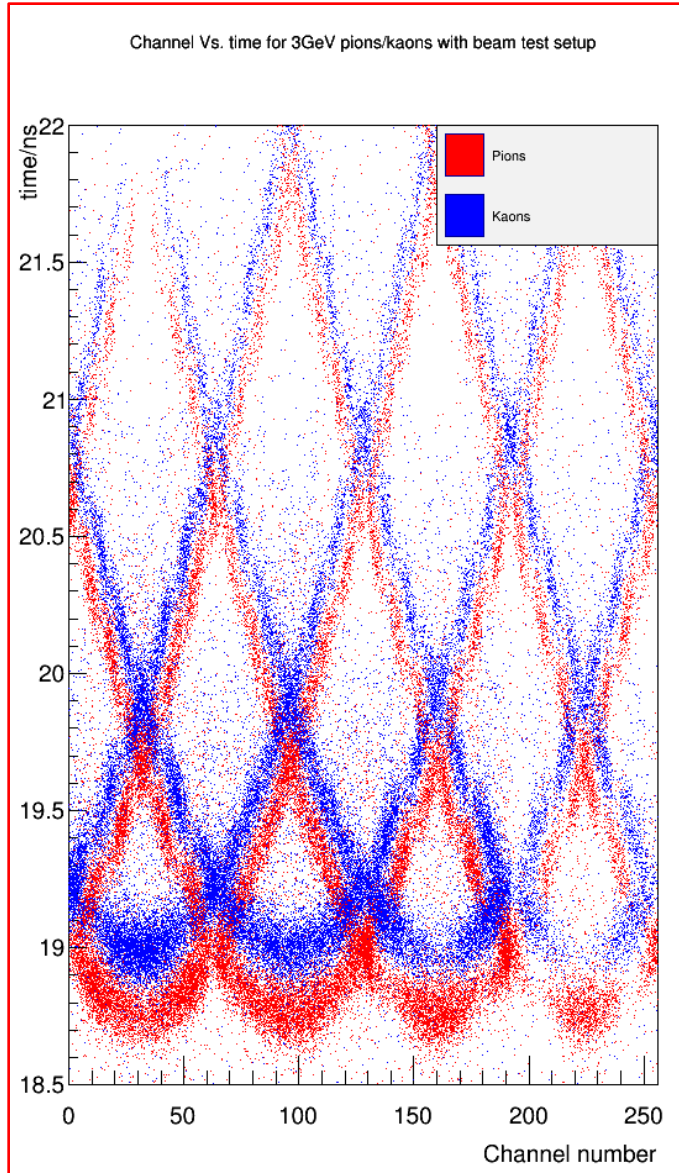
1x4 CFD Readout VME-based Caen TDCs



Event rate $\sim 5-10\text{Hz}$
 2x polar angles;
 1x off centerline (x=20)

iTOP relativistic velocity separation

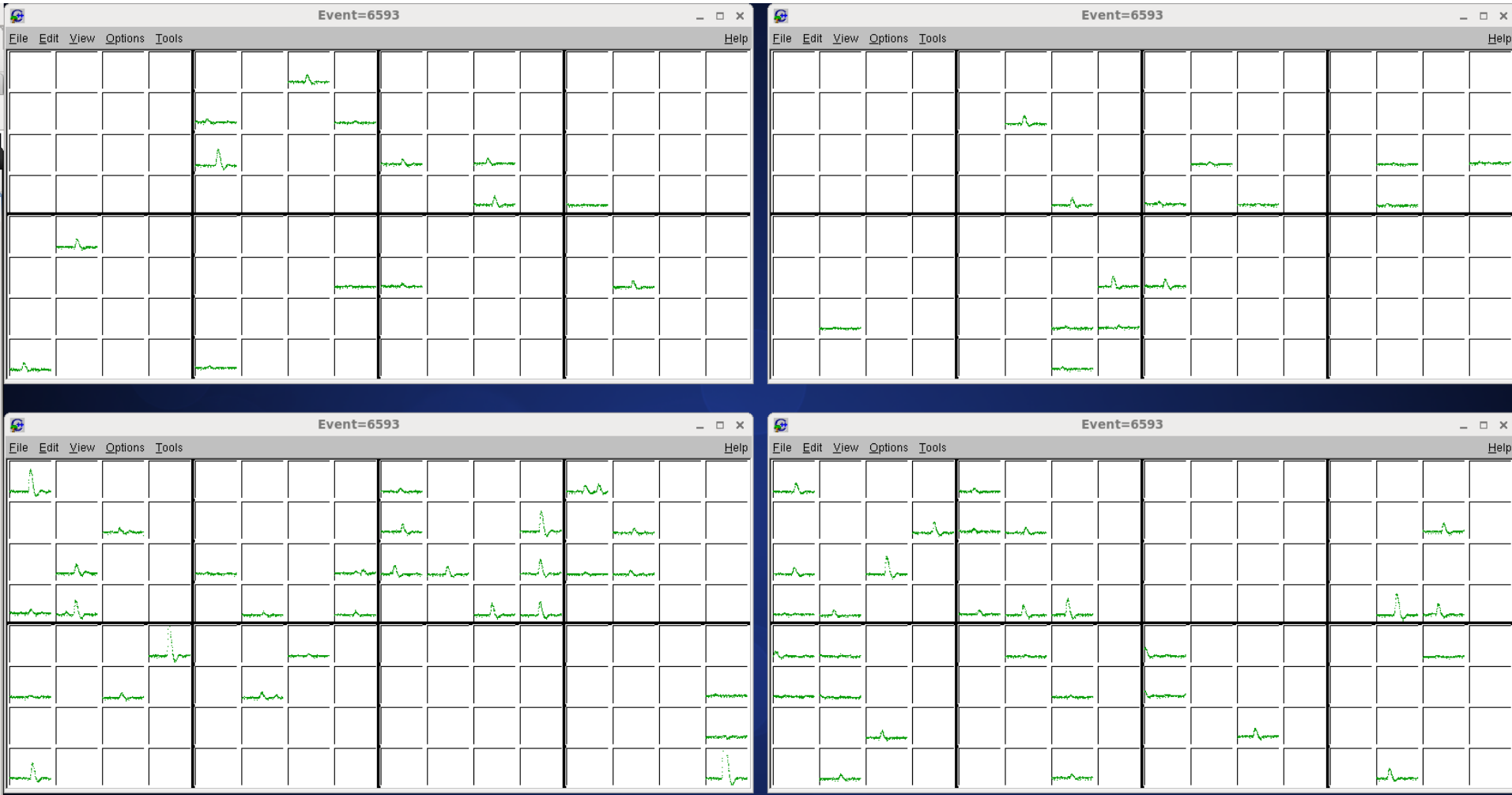
- Space-time correlations



Beam Test Data

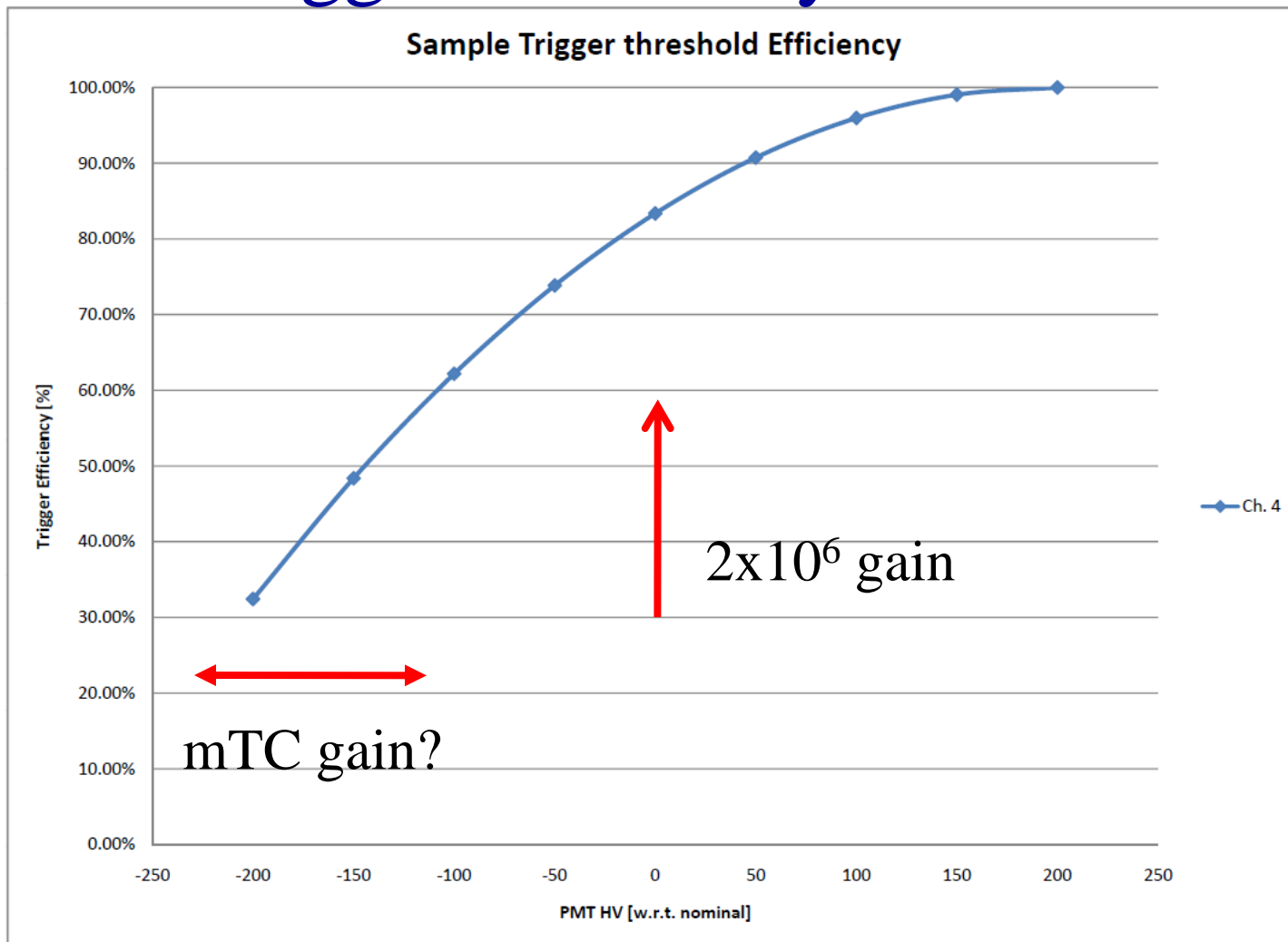
These are cumulative distributions

Typical LEPS Event



About 80% efficient, but running at very high gain!

Trigger Efficiency estimate

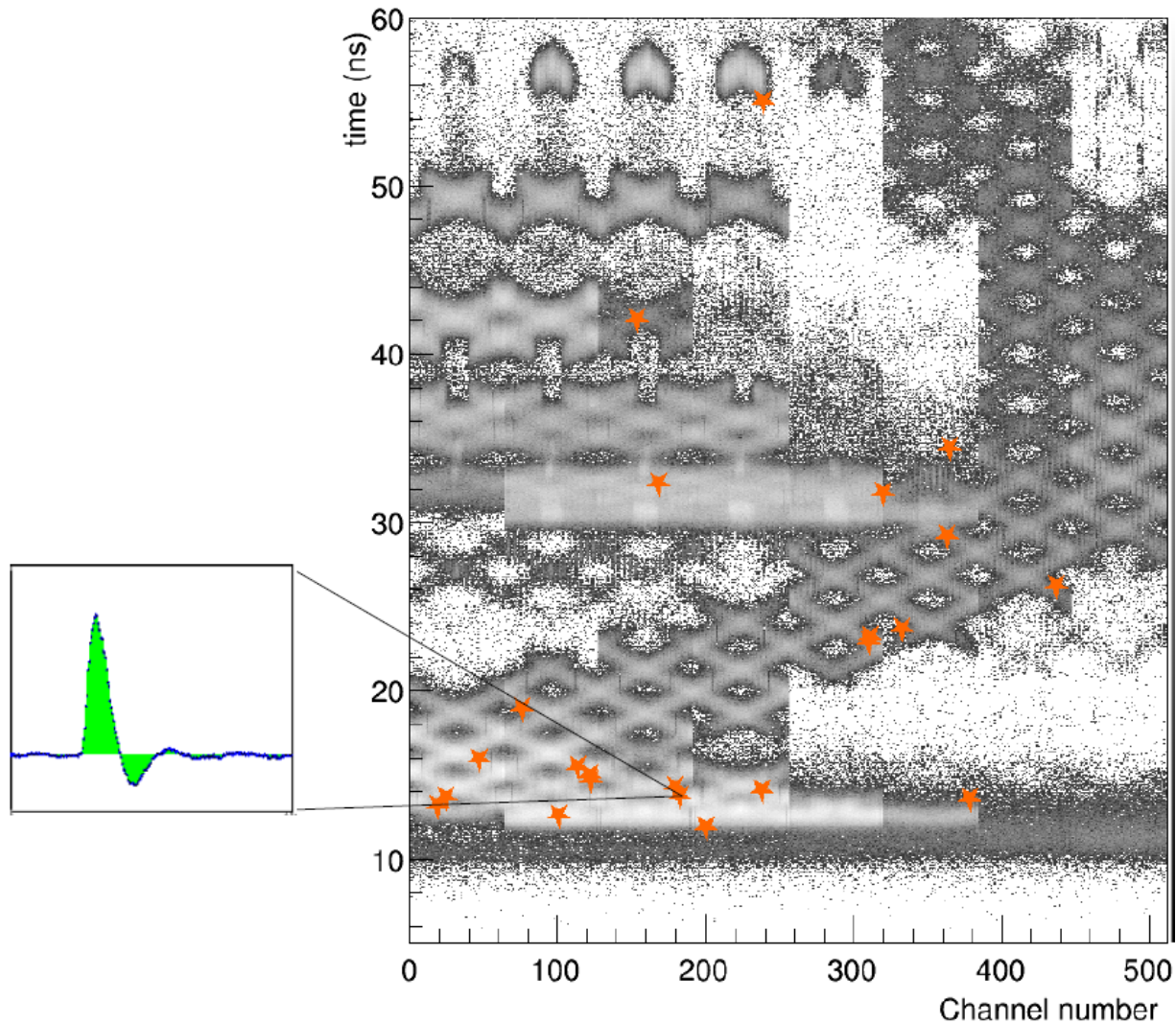


This is why I am very concerned – same electronics

For each event

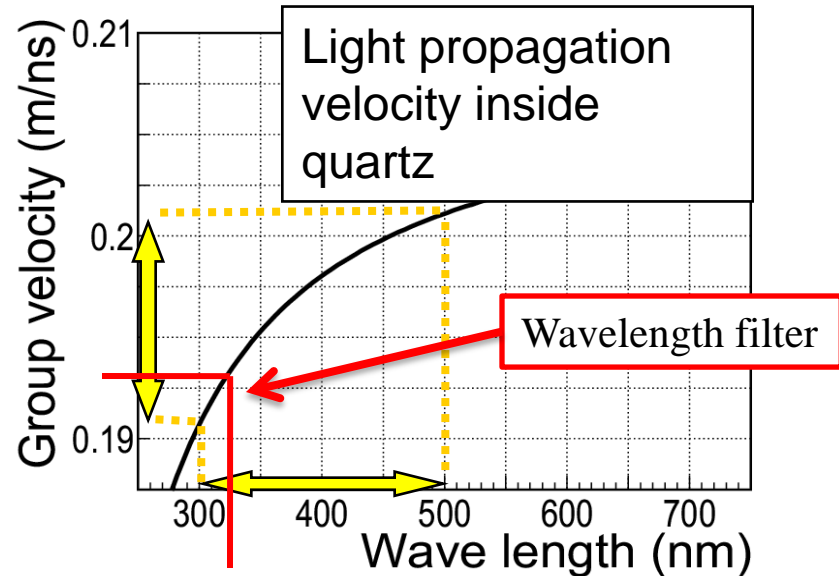
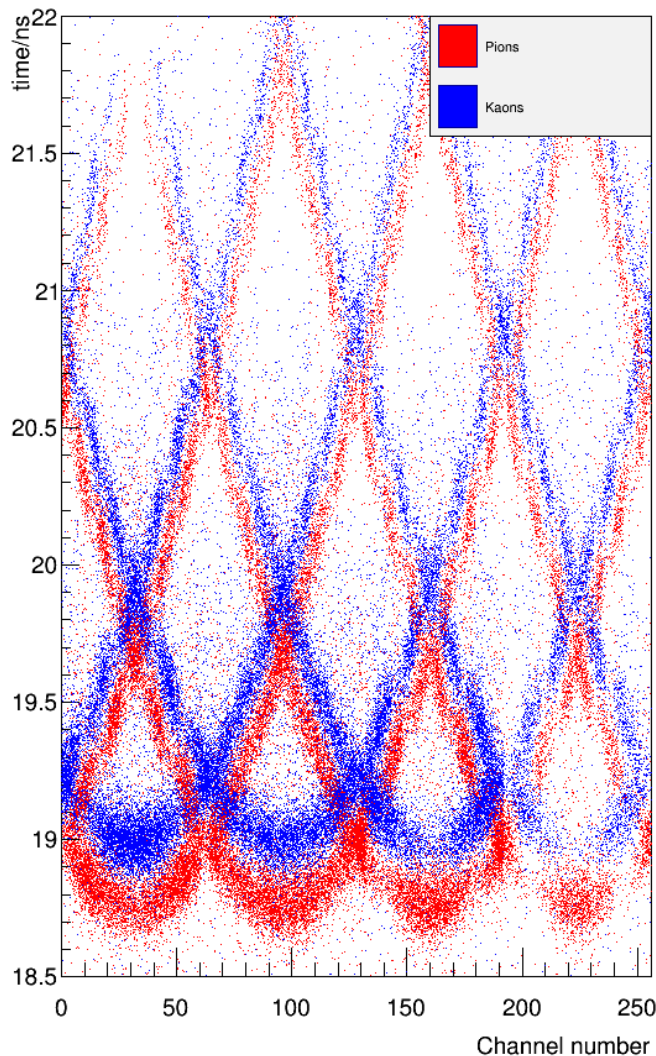
- Test most probable distribution

Beamtest Experiment 2 Run 568 Event 1



Temporal broadening

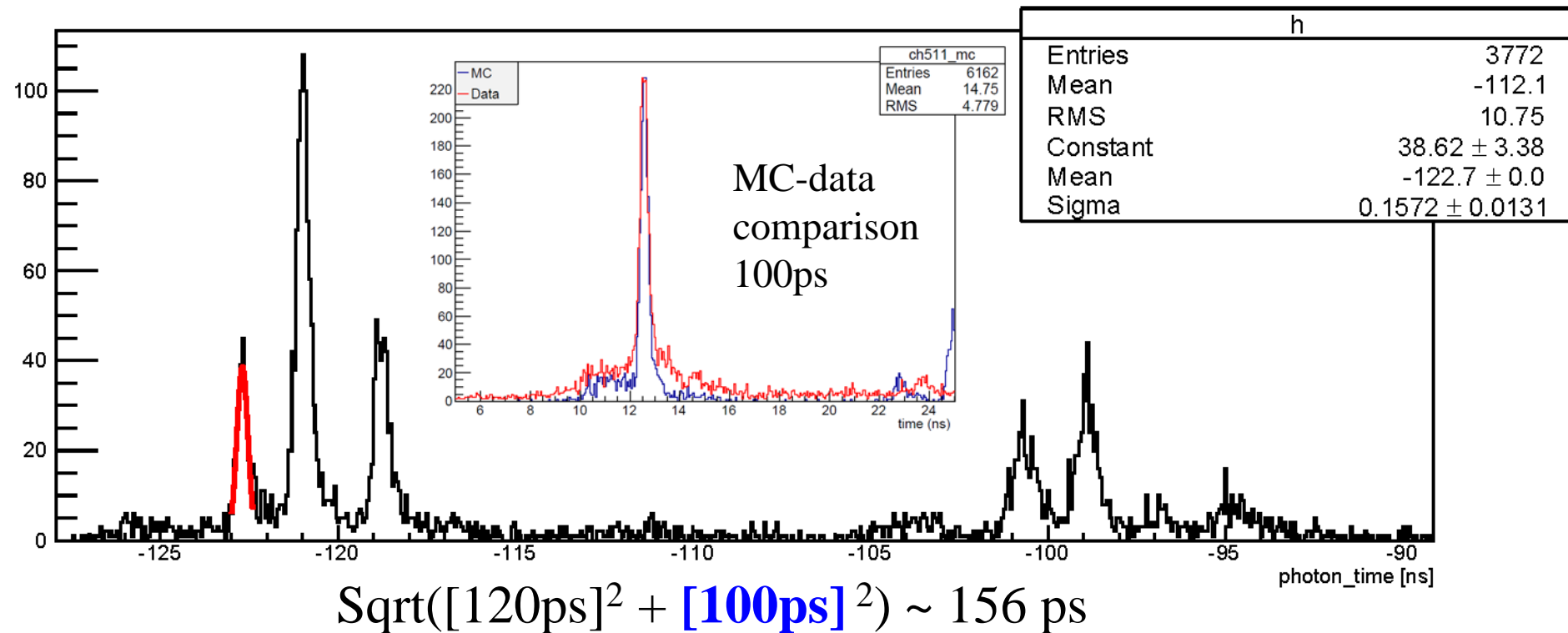
- Limited gain from improved time resolution
- Coarser spatial resolution integrates more of partial ring



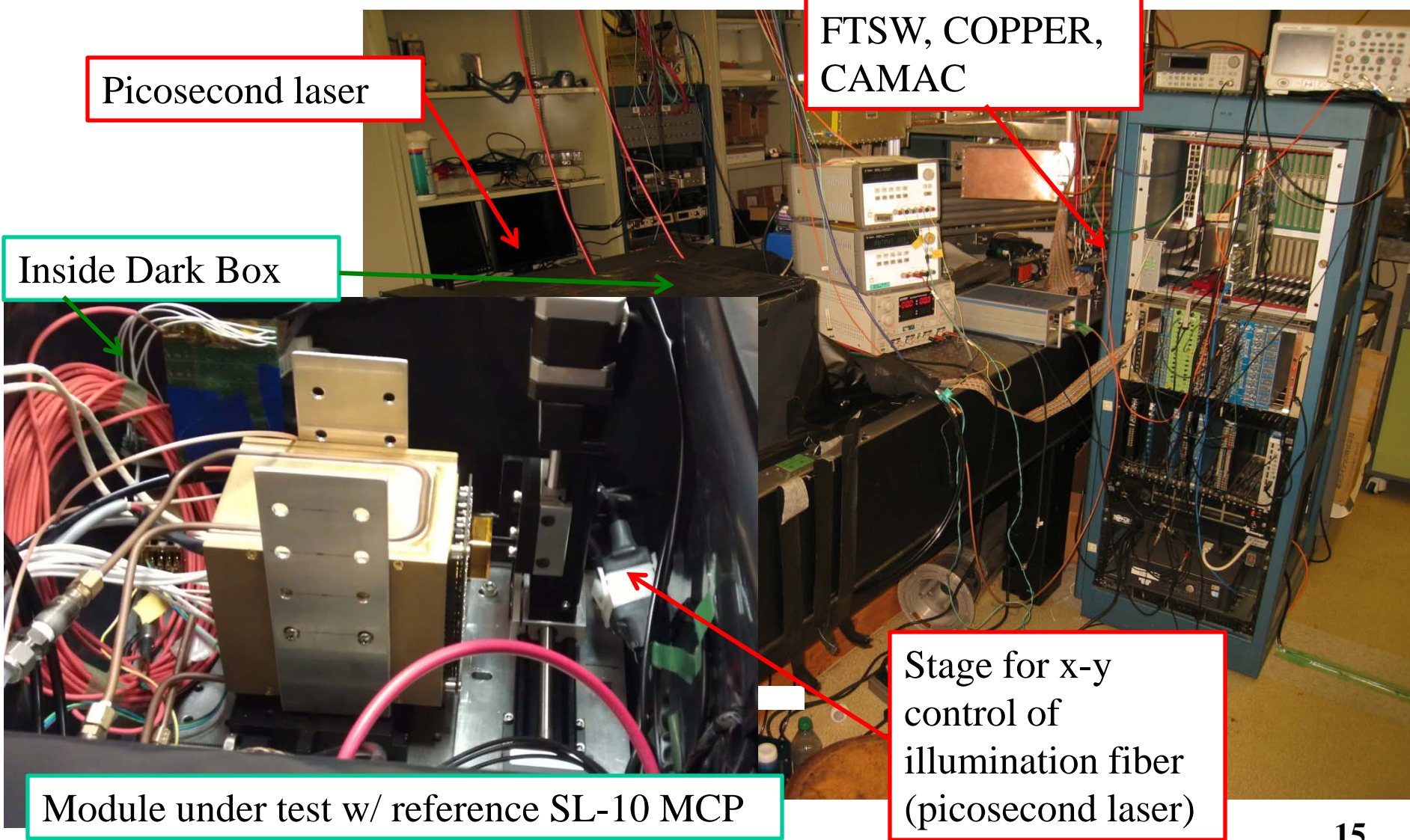
- Due to wavelength spread of detected photons
→ propagation time dispersion
- Longer propagation length
→ Improves projected ring image difference
But broadens time distribution

Measured Narrower Peaks Consistent with MC resolution + 100ps smearing

- For $\text{ADC} > 100$ and using the “120ps” width determined from GEANT4



Insufficient time/laser scanning resources before LEPS beamtest – subsequent testing in Hawaii



Picosecond laser

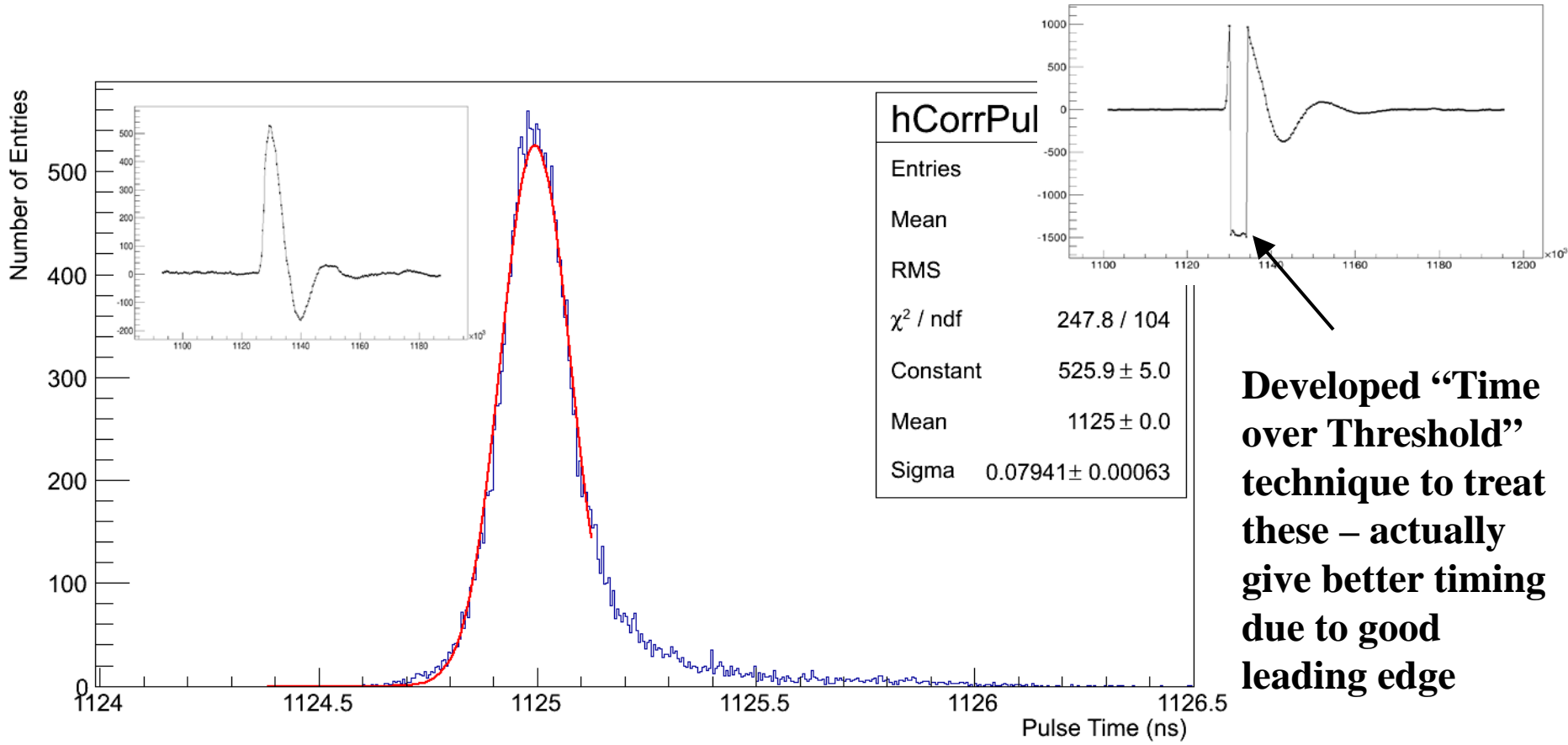
FTSW, COPPER, CAMAC

Inside Dark Box

Stage for x-y control of illumination fiber (picosecond laser)

Module under test w/ reference SL-10 MCP

Example single photon* timing, no ADC cuts, no modifications from LEPS configuration

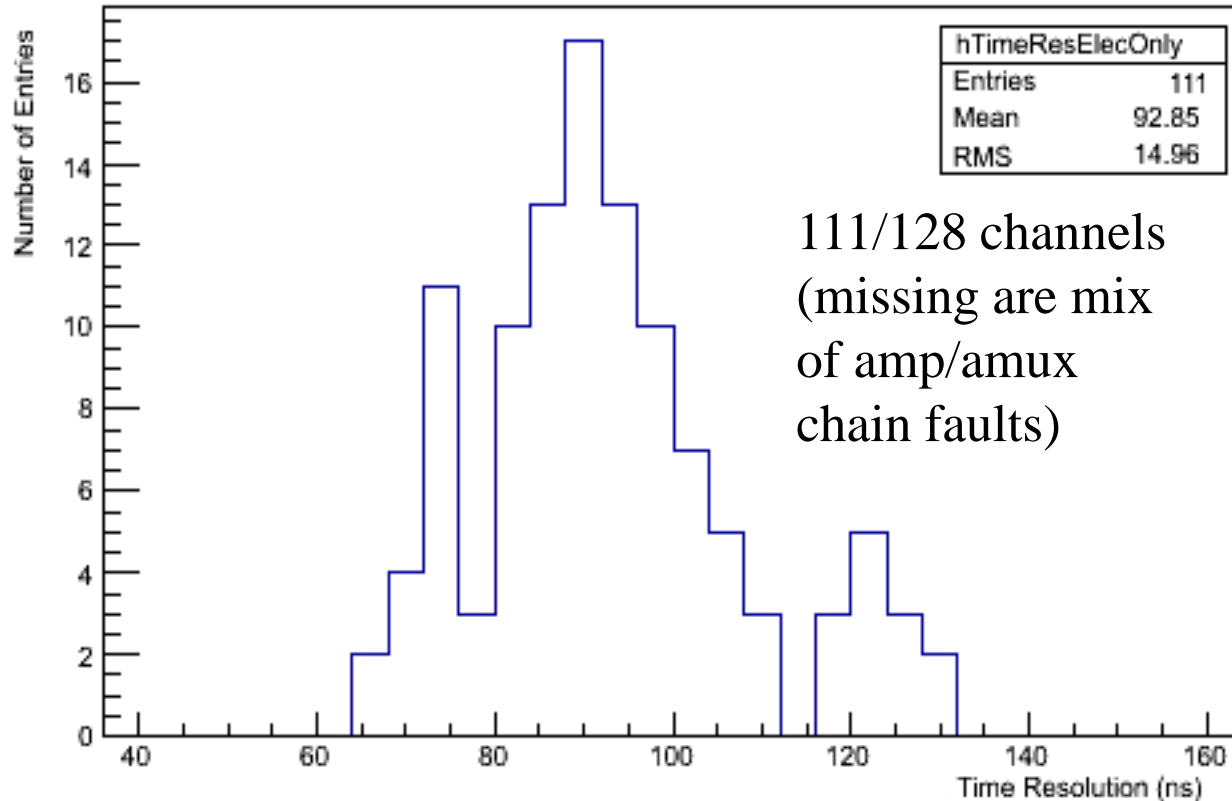


Developed “Time over Threshold” technique to treat these – actually give better timing due to good leading edge

~97% analysis efficiency (3% window “wrap around” cut [recoverable] – FTSW artifact)

* $\leq 5\%$ occupancy

Board Stack #37 single photon* timing, no ADC cuts, no mods from LEPS configuration**



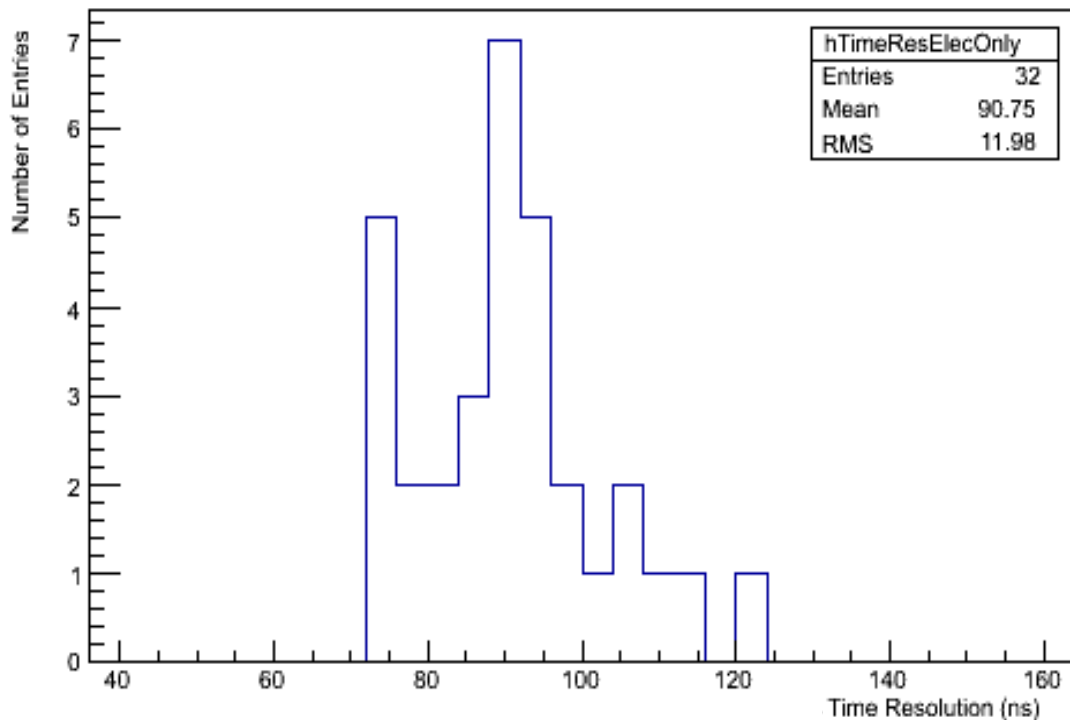
~25ps
CAMAC
contribution
removed (in
quadrature,
not relevant
for Belle II)

93 +/- 16 ps [a couple bad ASICs dominate high-end outliers]

* <= 5% occupancy

** most channels reworkable, didn't have time

Test system @ LEPS had 4 modules

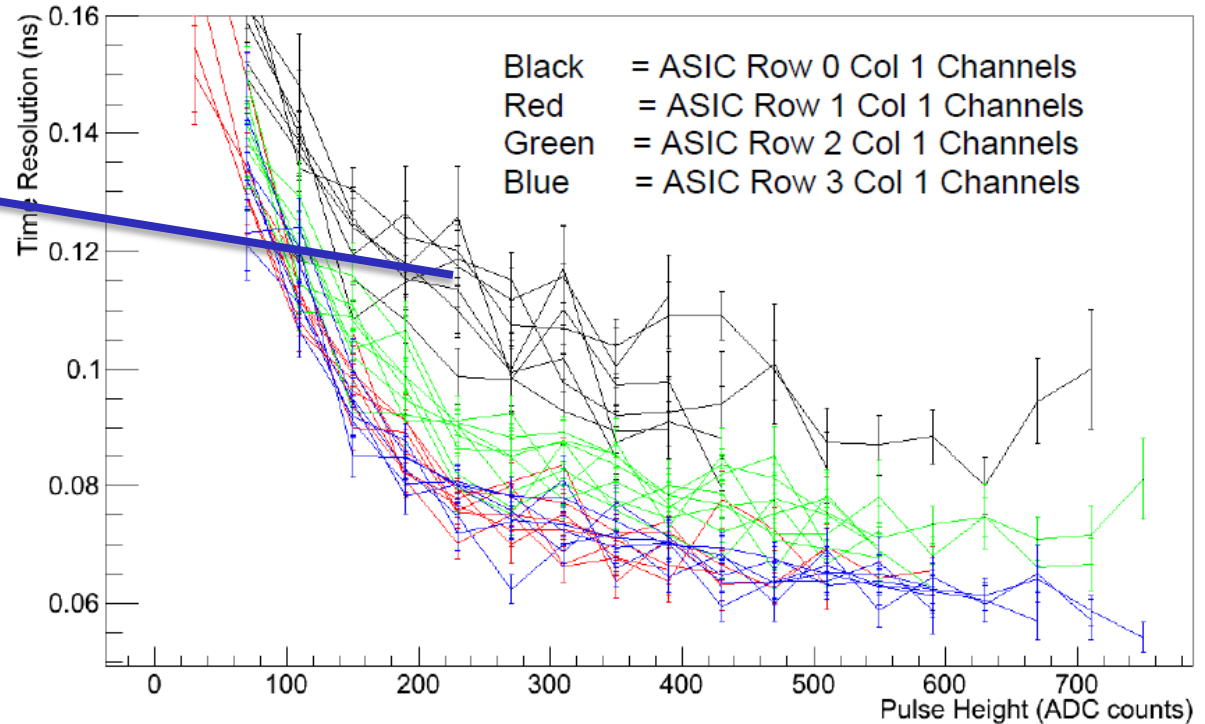
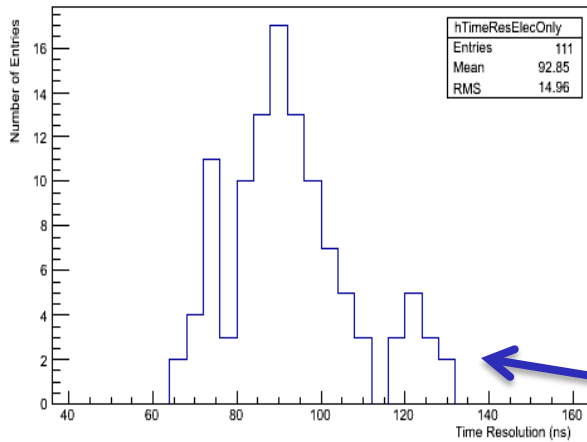


**In progress,
reporting 32/64
ASICs (2 of 4
modules)**

**Same conditions,
1x channel (Ch. 6)
per ASIC**

91 +/- 12 ps [bad ASICs only get to vote once, Ch. 6 not worst]

What limits resolution? Why large scatter?



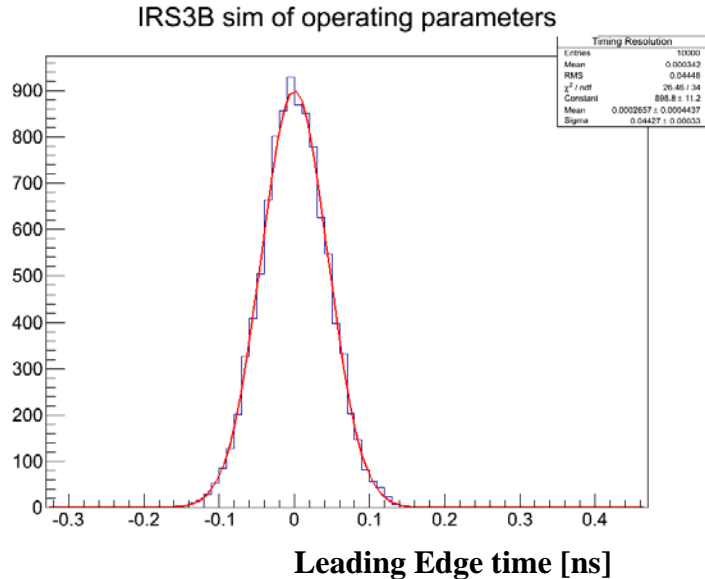
- **Amplitude dependence similar**
- **Channels on same ASIC have similar limiting resolution**

Understanding Expectations: IRS3B “toy” Monte Carlo

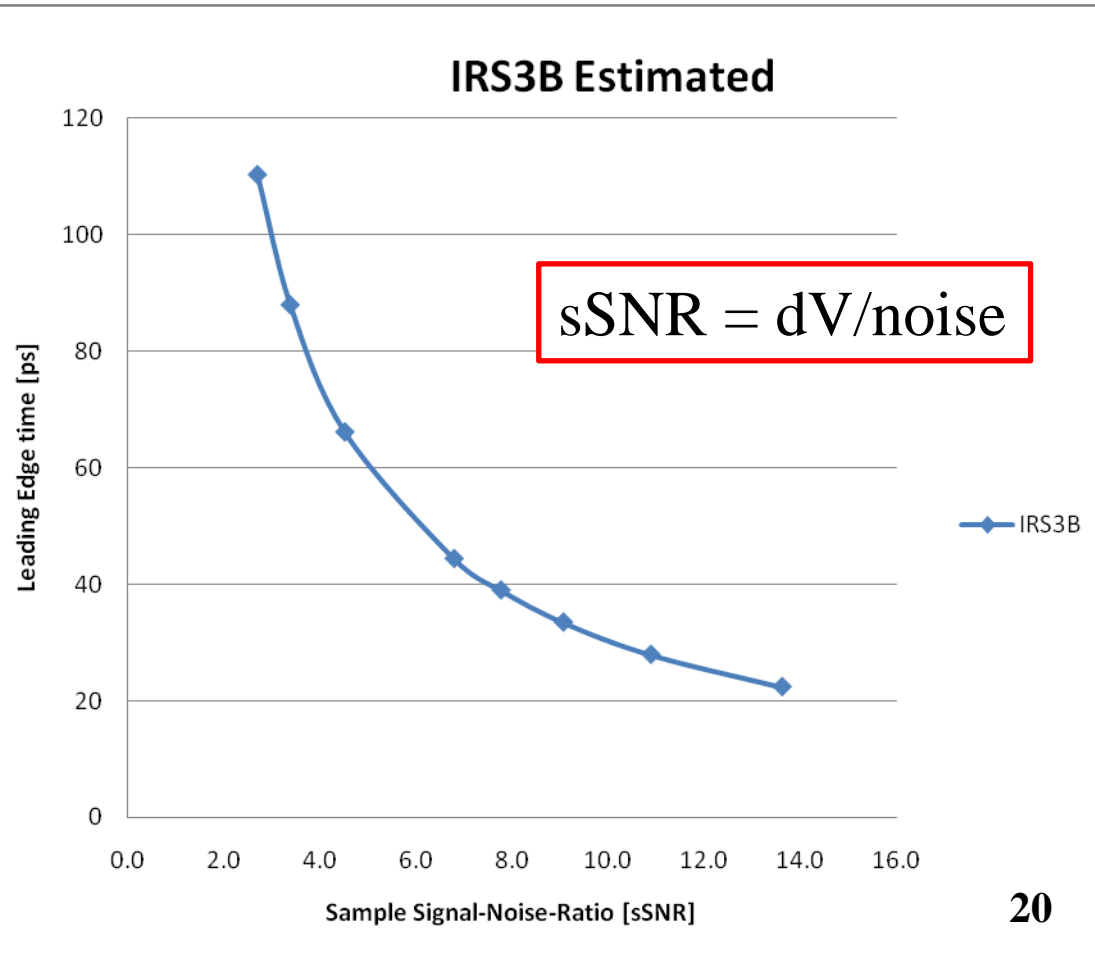
Vpeak 100 ADC
Risetime 2.7 ns
Sampling rate 2.72 Gsa/s
nom dT 0.368 ns
nom dV 13.617 ADC/sample

40% CFD ratio:

Applied between 2 points on leading edge that bracket this transition



~44ps for 100mV peak,
2mV noise



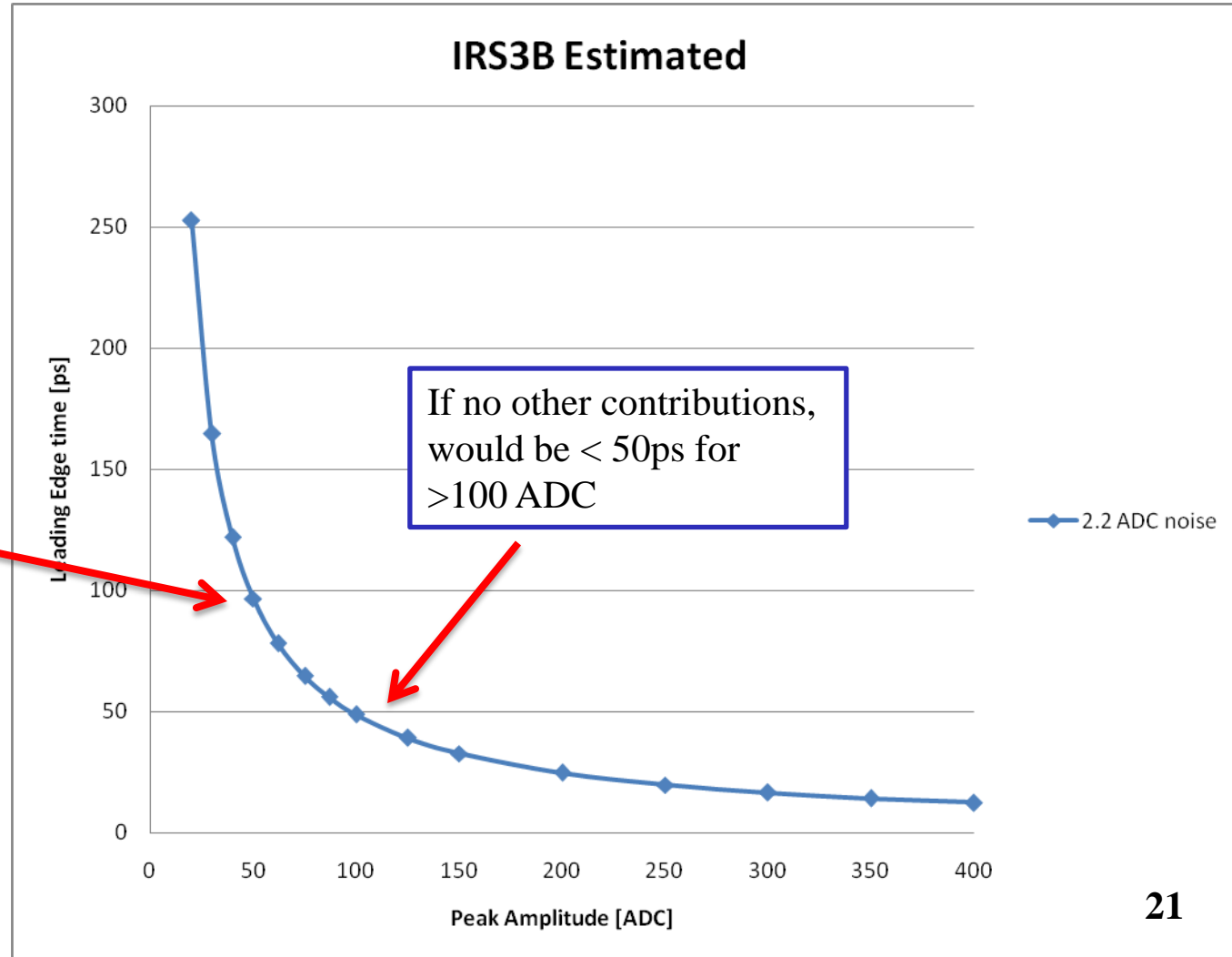
In general, noise is constant: $SNR \sim S * C$

Noise 2.2 ADC
Risetime 2.7 ns
Sampling rate 2.72 Gsa/s
nom dT 0.368 ns

40% CFD ratio

Even in ideal case, for only using 2 points on leading edge, need $V_{peak} \geq 50$ ADC to get below 100ps timing

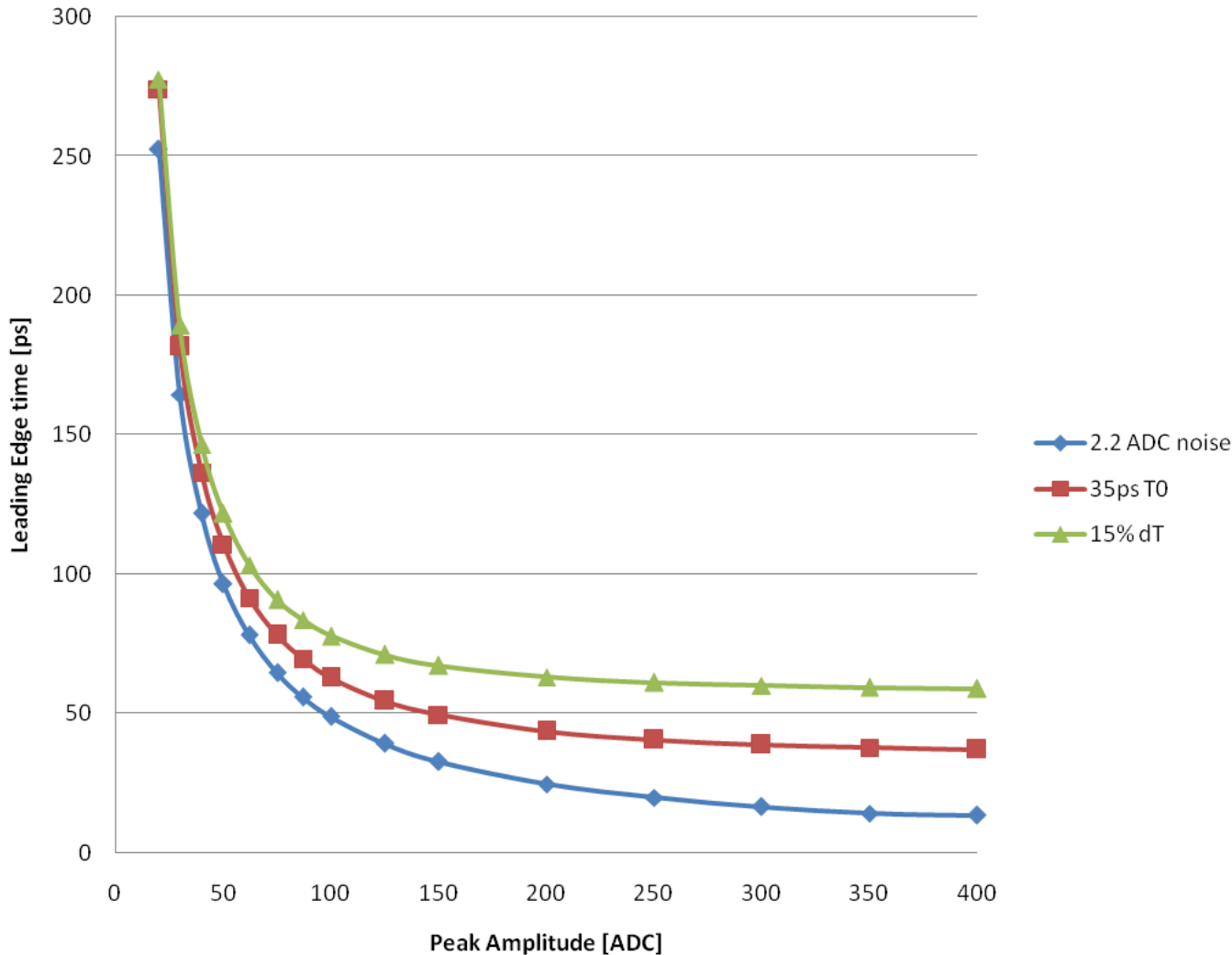
(gain issue)



Adding in realistic degradations

40% CFD ratio

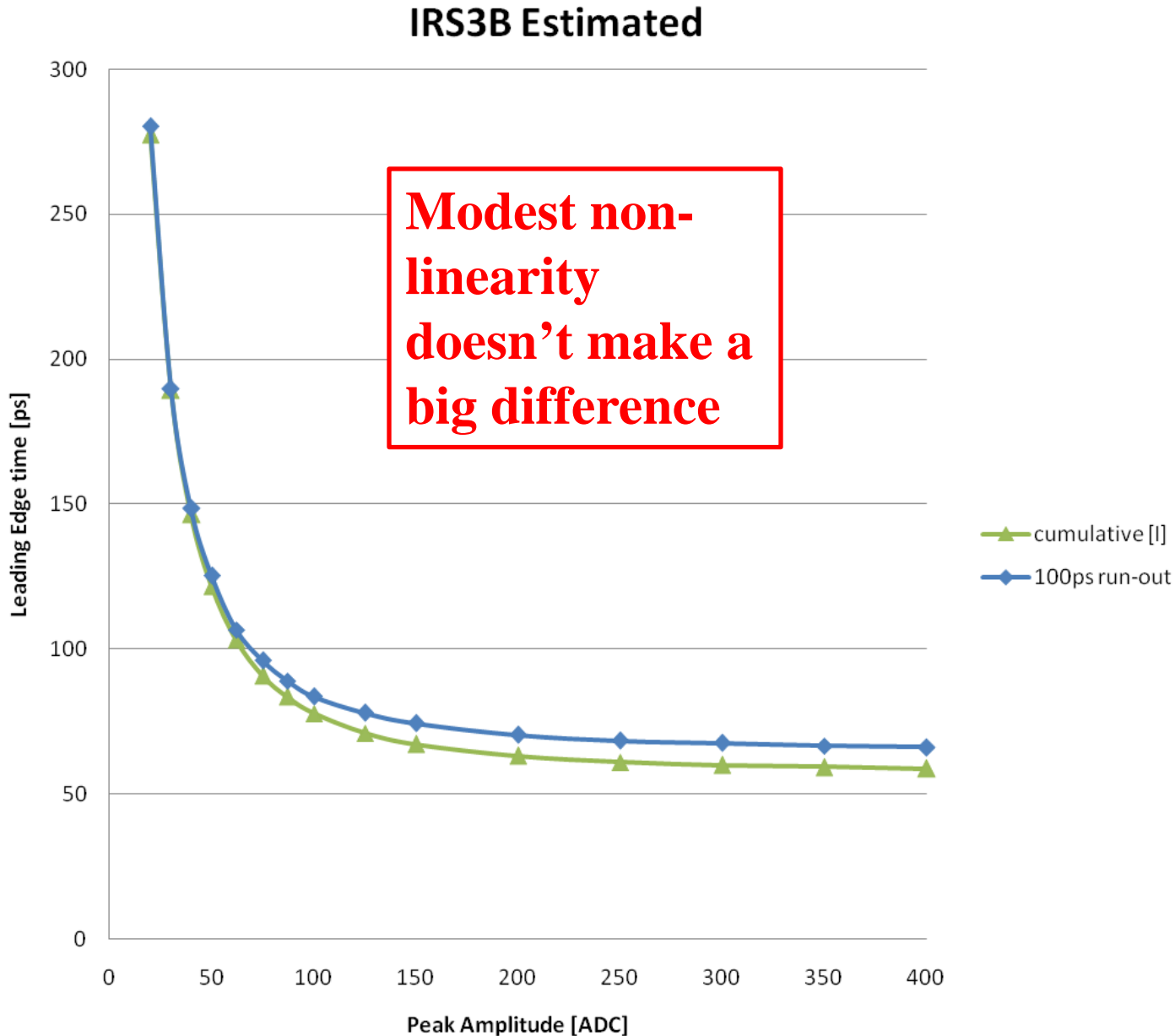
IRS3B Estimated



**What effects
still missing?**

- Residual Timebase jitter ?
- Non-linearity on leading edge?
- Something else ?

Adding in realistic degradations (II)

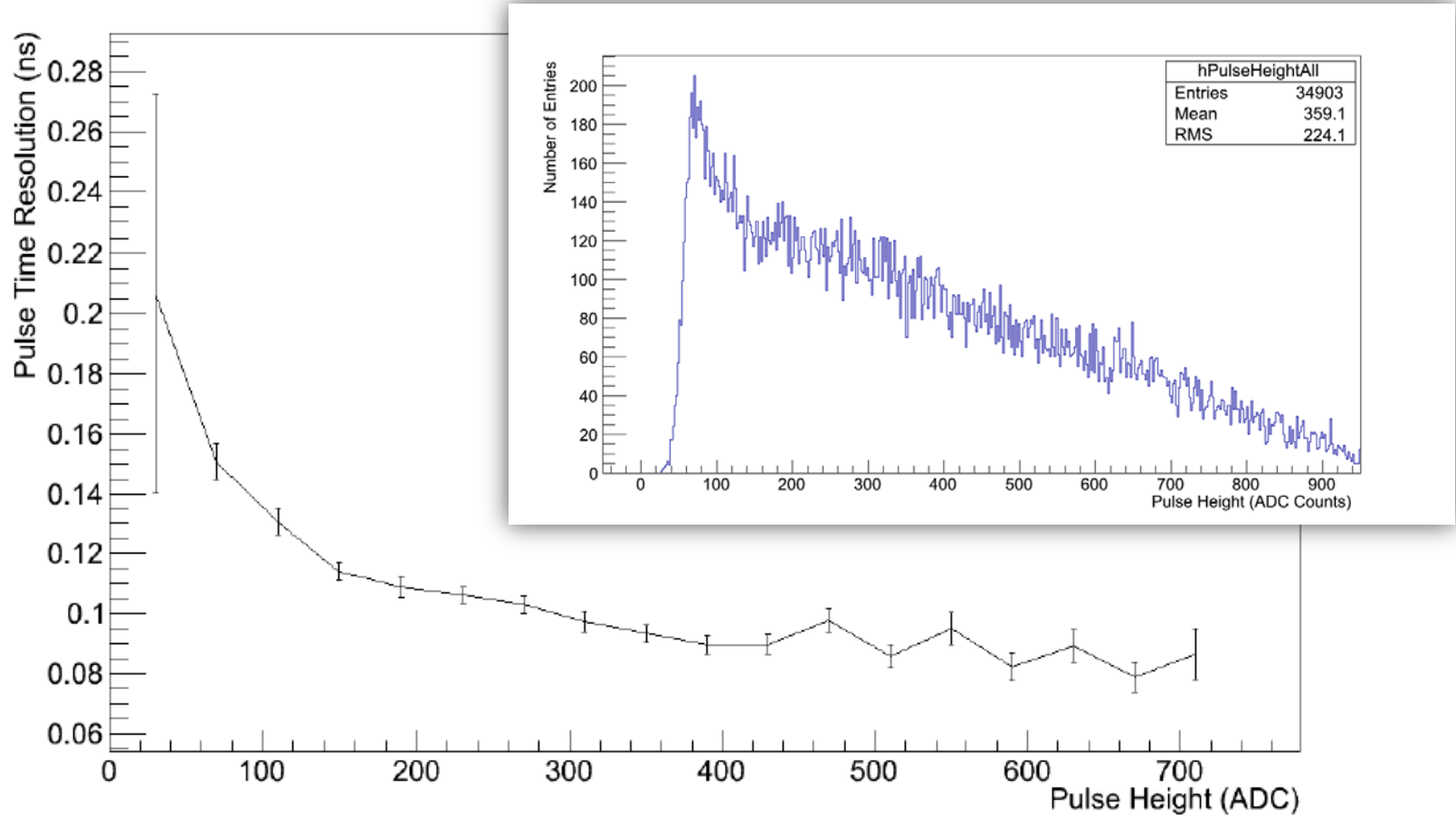


**What effects
still missing?**

**Amplifier
noise?**
(doesn't
impact
pulser or
sine data)

What remains to get to $\leq 50\text{ps}$?

1. Increased Amplification



Want >100 ADC counts ($>\sim 60\text{mV}$) for smallest pulses

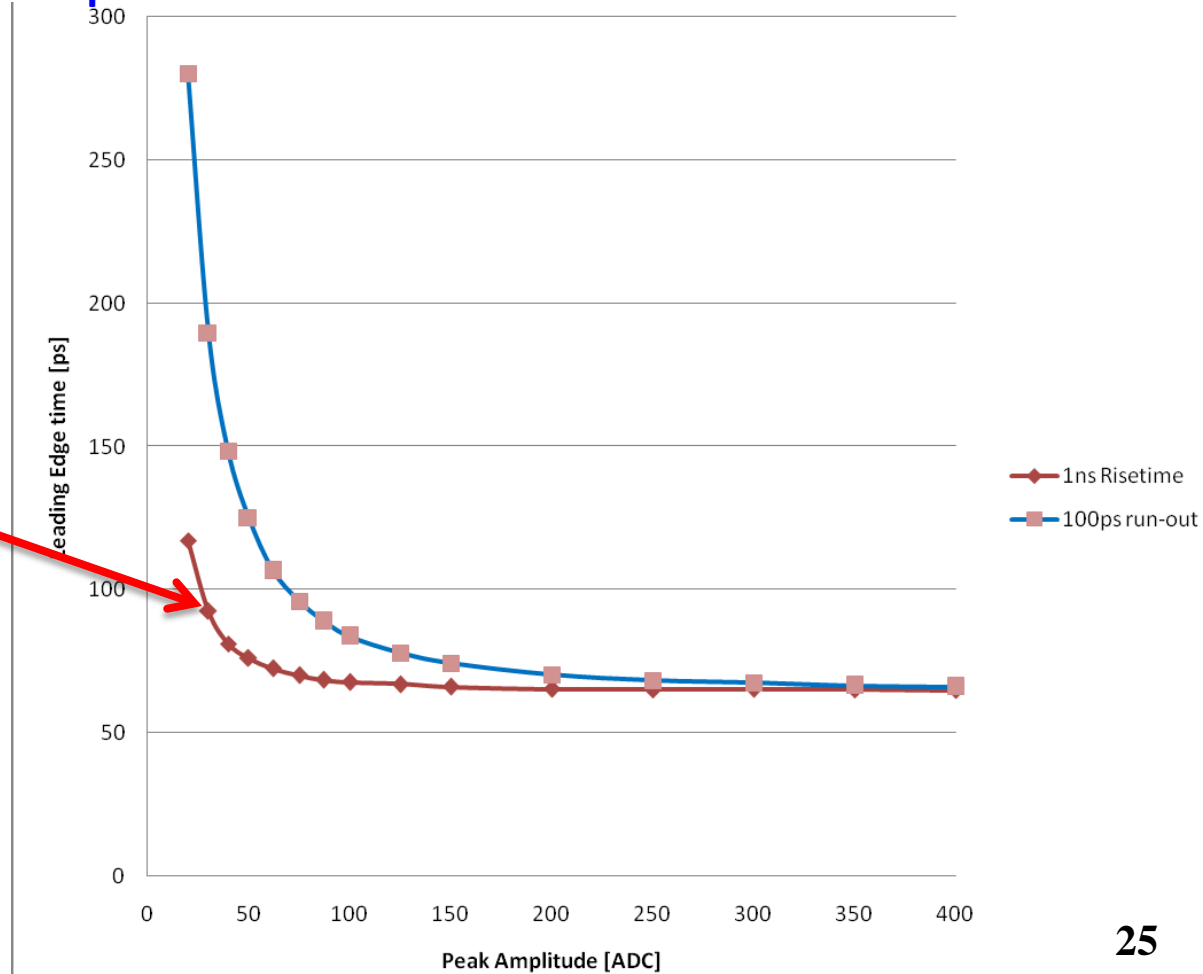
2. Improved Risetime

V_{peak} 100 ADC
Risetime 1.0 ns
Sampling rate 2.72 Gsa/s
nom dT 0.368 ns
nom dV 13.617 ADC/sample

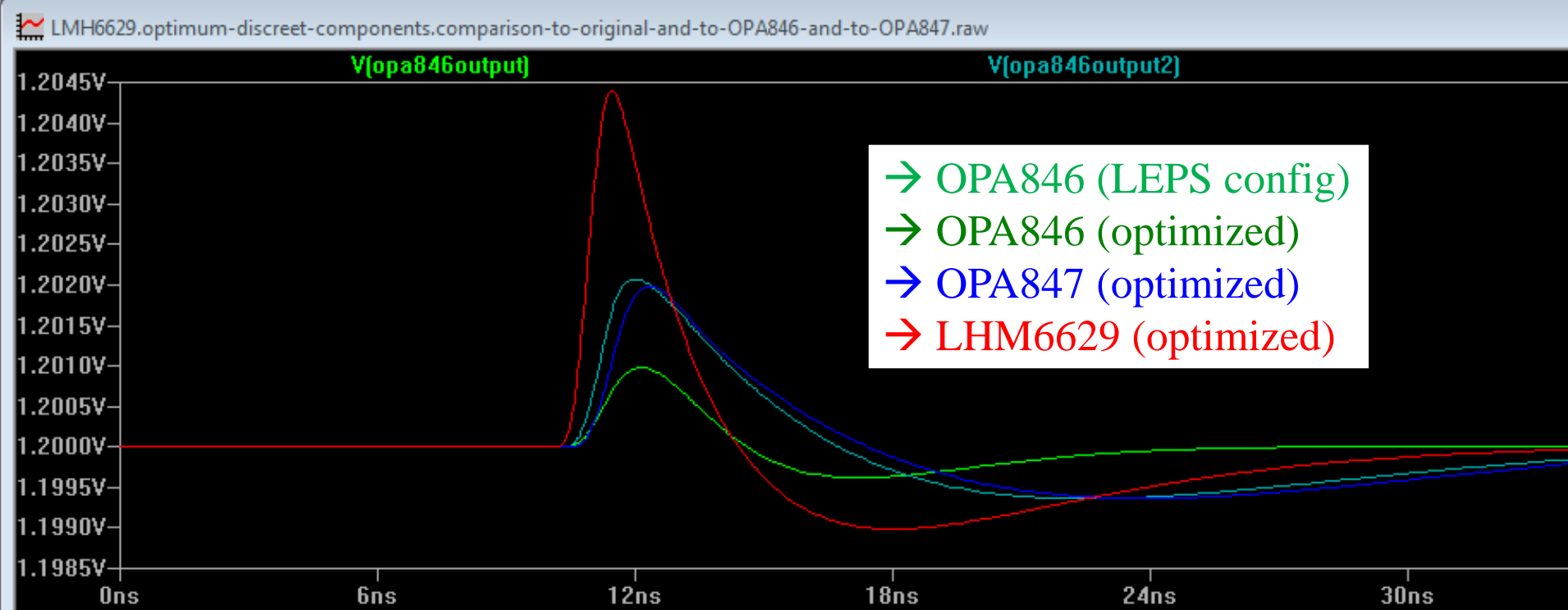
40% CFD ratio

Now < 100ps
for ADC>30
(with no other
changes)

Increasing amplitude
and risetime has
similar effect – will
do both



Improved Amplifier Choice

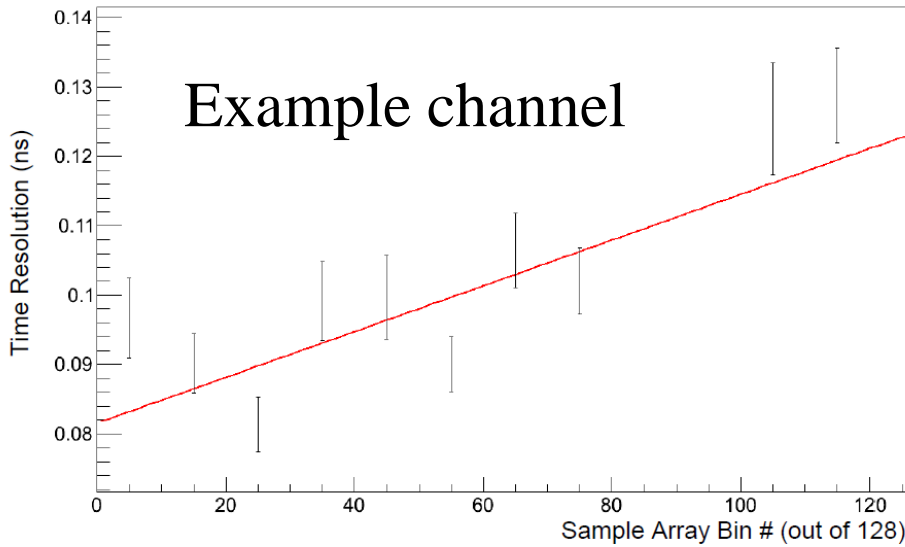


Simulation indicates -- prior to changing layout radically (2x stage design), can already improve amplitude/risetime by switching to **LHM6629** (single stage)

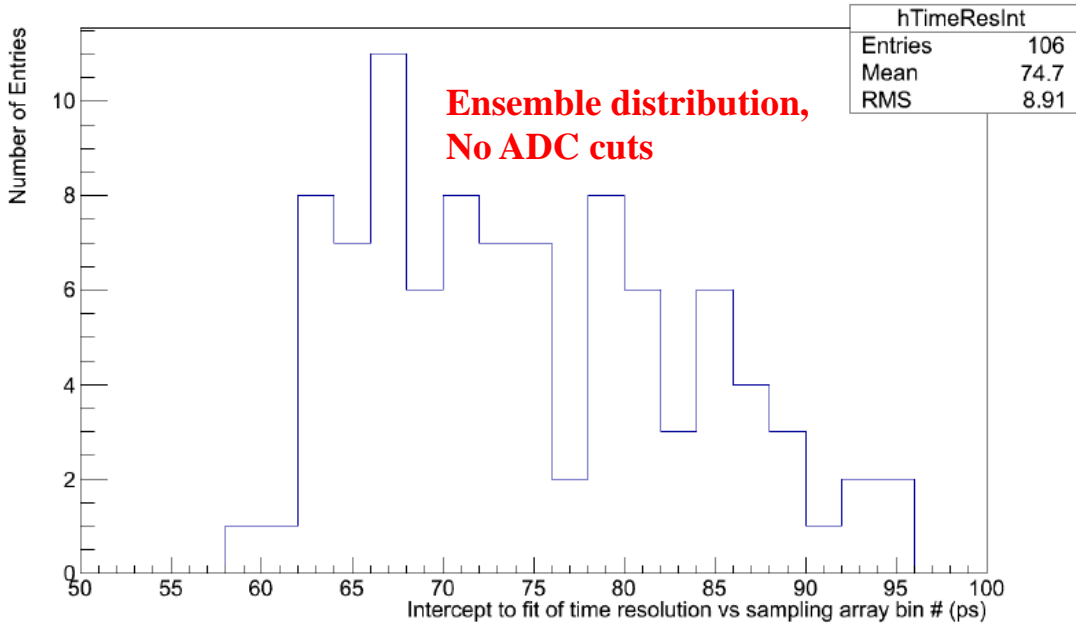
4x gain, >2 faster risetime

3. Improve Timebase Stability

A combination of jitter (noise on VadjN) and coarseness of DAC are the primary contributors



Time Resolution Vs. Sampling Array Bin # Intercept Distribution



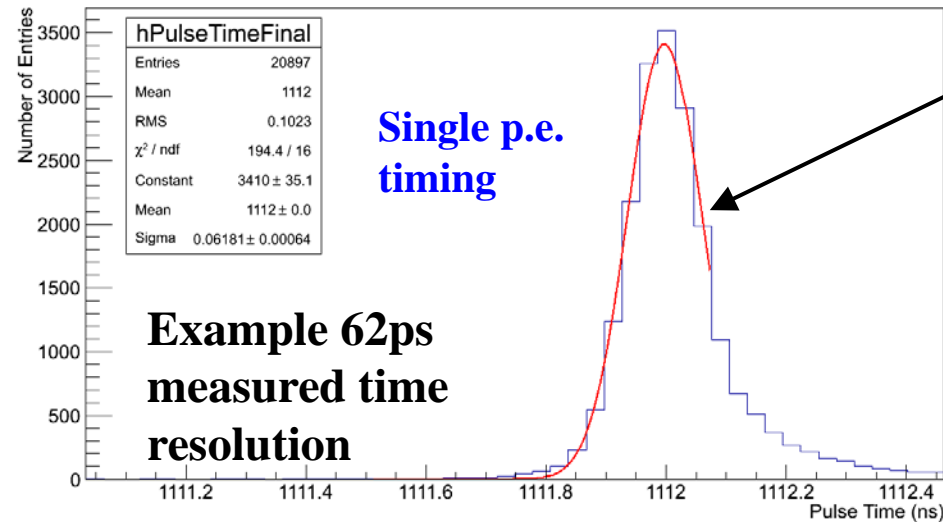
100ps Average



75ps Average

- Plot distribution of intercepts from linear fit to time resolution vs. sampling array bin # plot
- Represents time resolution if there was no degradation along sampling array

Improved amp, calibration



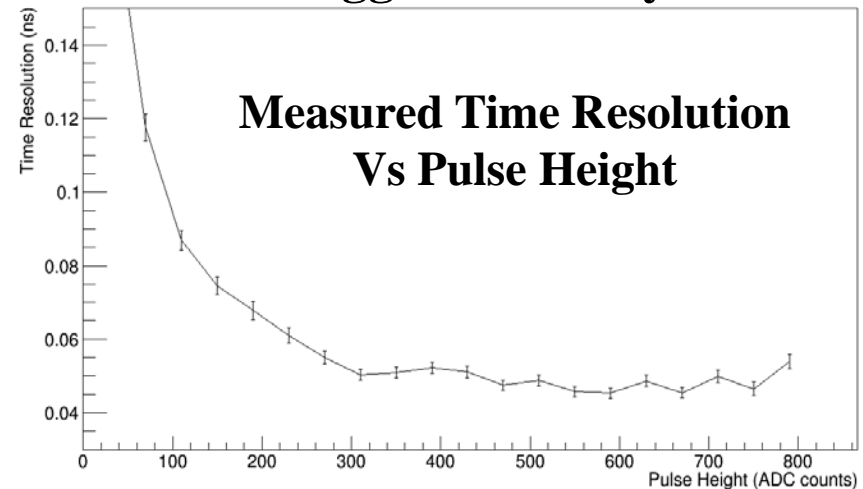
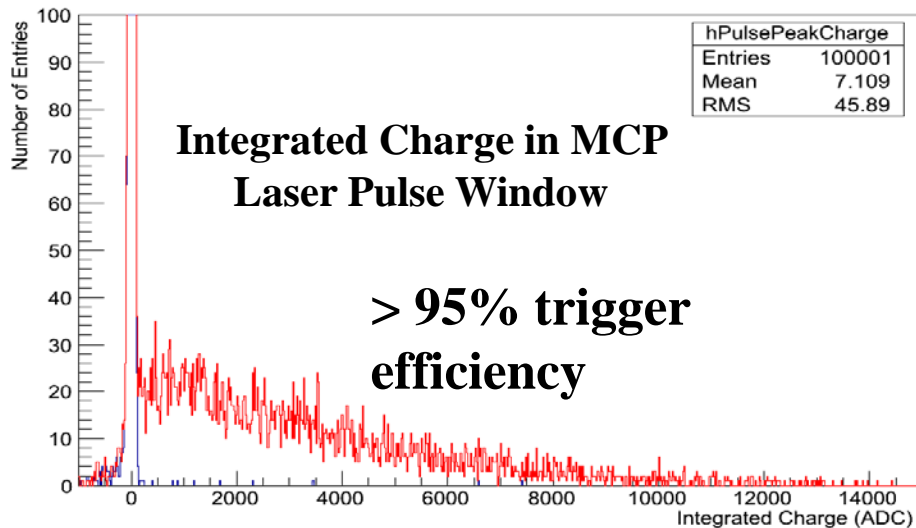
Measure time resolution in core distribution

- Trailing tail expected from photoelectron backscatter within PMT
- Also leading non-Gaussian tail due to small pulses

Requirement: <100ps

Goal: 50ps with higher gain

LEPS beam test: ~100ps timing, 77-86% trigger efficiency



• Brian will talk about calibration specifics tomorrow

Summary – Day 5

Some additional information provided

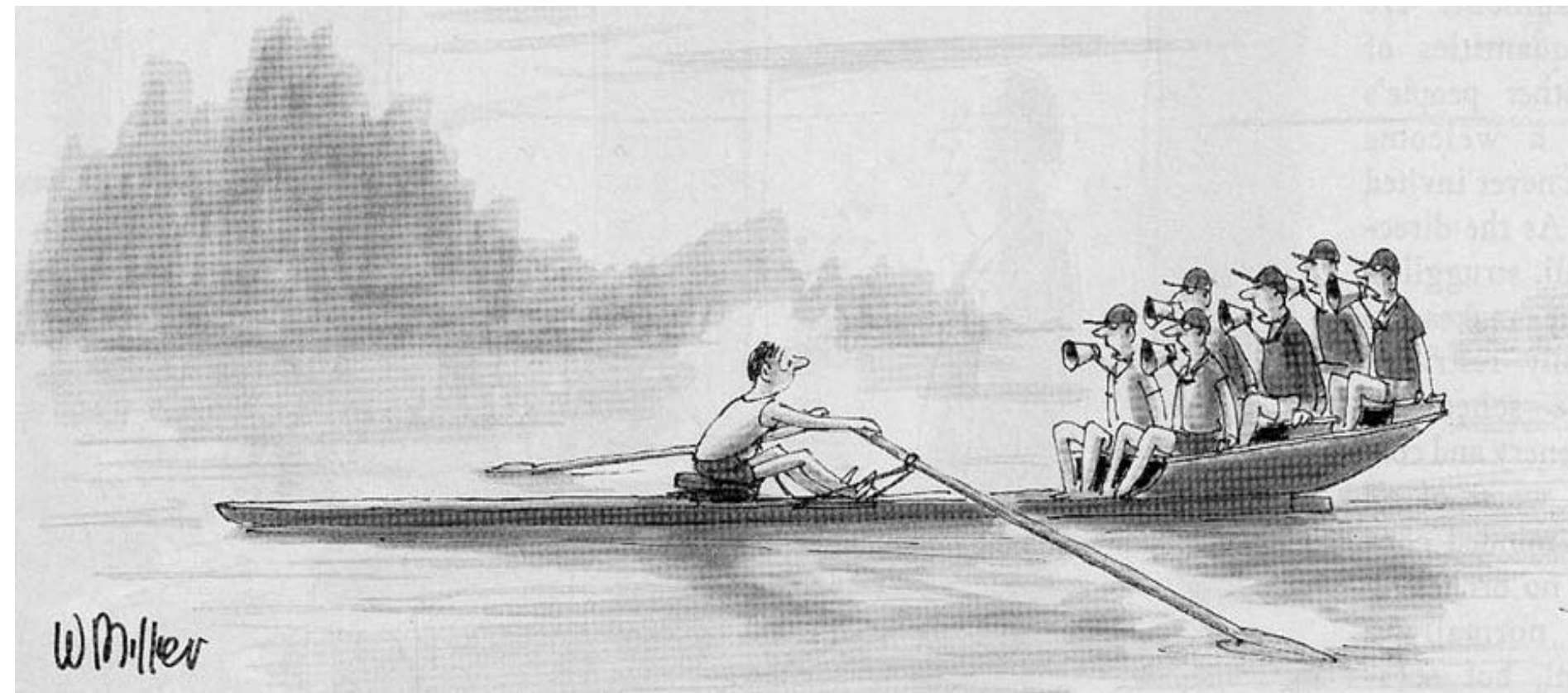
- **Go through list of items from last time (next slide)**
- **All of these concepts are straightforward, though much, much, much to be assimilated all at once**
- **Brian Kirby will take you through calibration process tomorrow**
- **Essential issues to be addressed for quality mTC data-taking:**
 - **Are register configurations/feedbacks being set properly ?**
 - **Can we tell ? (meaningful DQM tools ?)**
 - **Understanding what is being done ?**
 - **Calibration! (and diagnostics)**

Specific DQM Needs

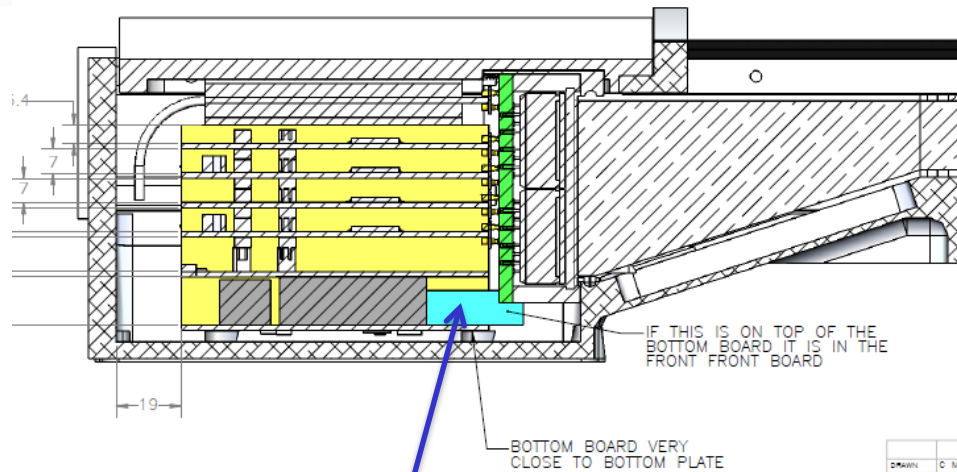
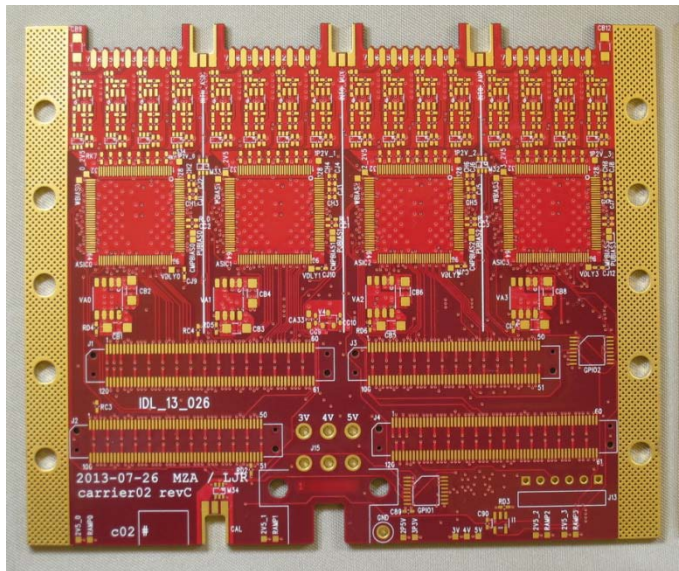
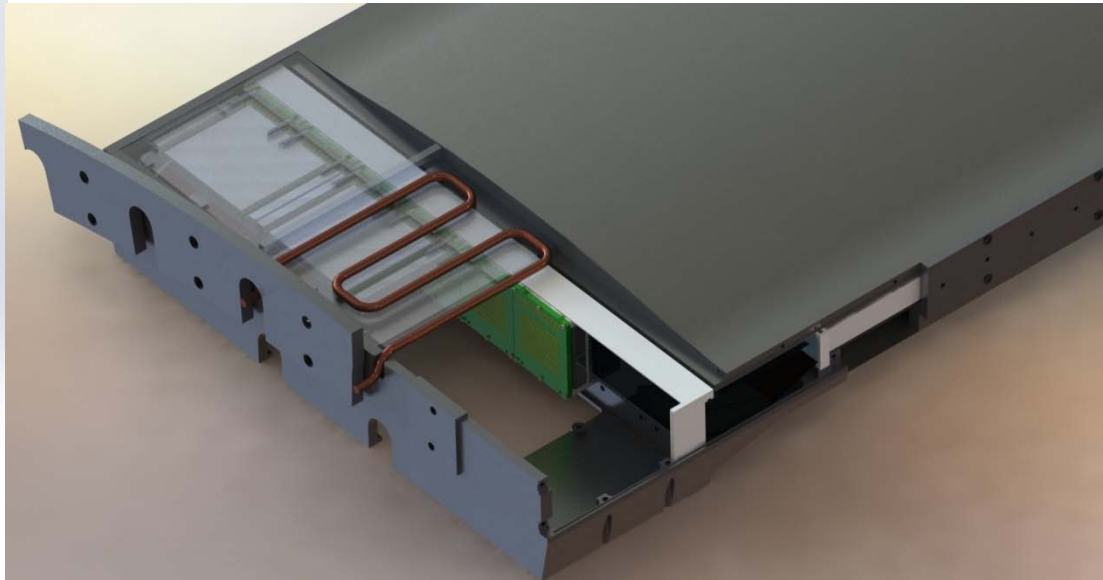
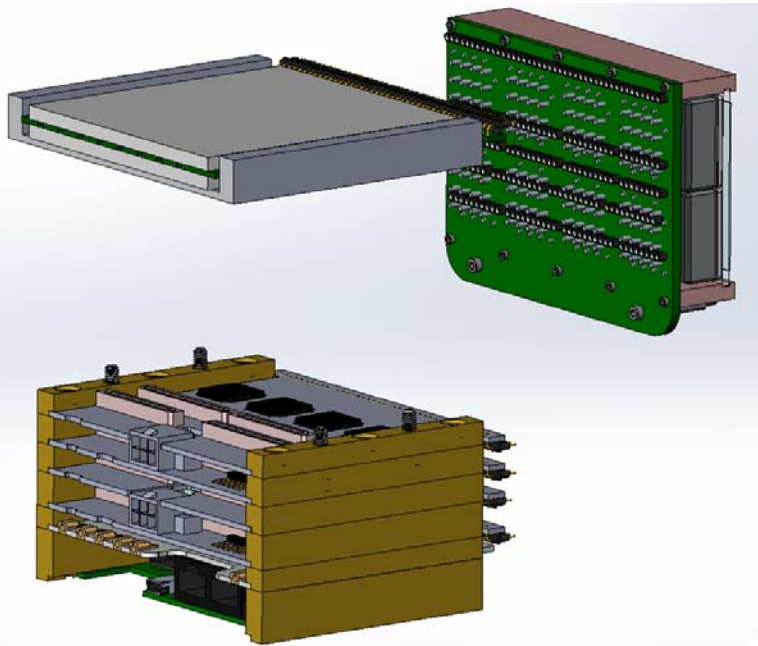
- **As data being accumulated:**
 - **What are best estimates of:**
 - ✓ **Pedestal residual (flag bad windows)**
 - ✓ **Sampling rate**
 - ✓ **Average (normalized) pulse width versus sample number [and across window seam]**
 - ✓ **Window dT**
 - ✓ **Channel hit occupancy**
 - ✓ **Pulse height spectra by channel, by PMT and by event**
 - ✓ **Event “time zero” mean and moment**
 - ✓ **Time offsets between modules and between clock fanout branches**



Back-up slides



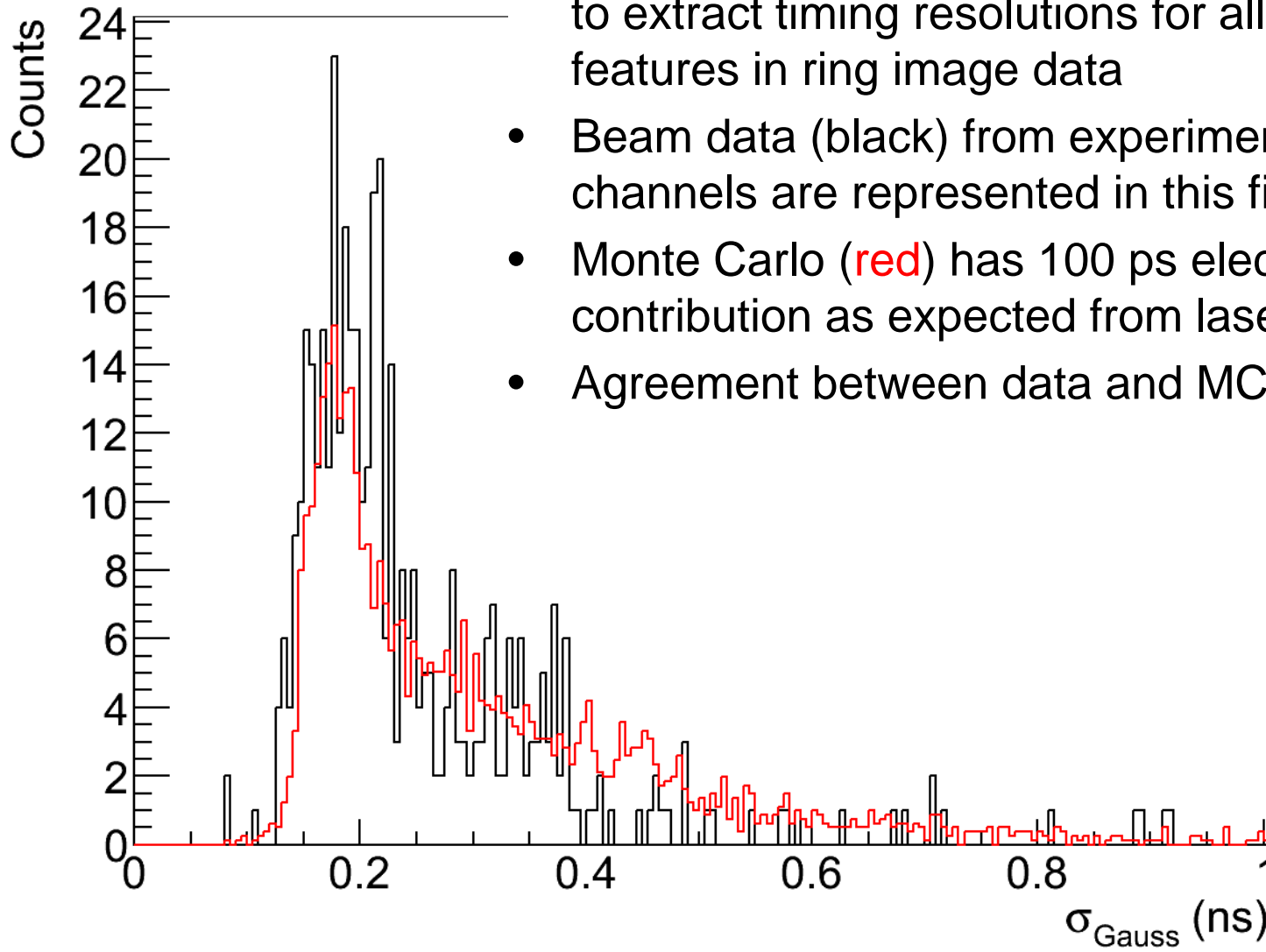
Final Board Stack Mechanics



1 last mechanical conflict: fiber transceiver

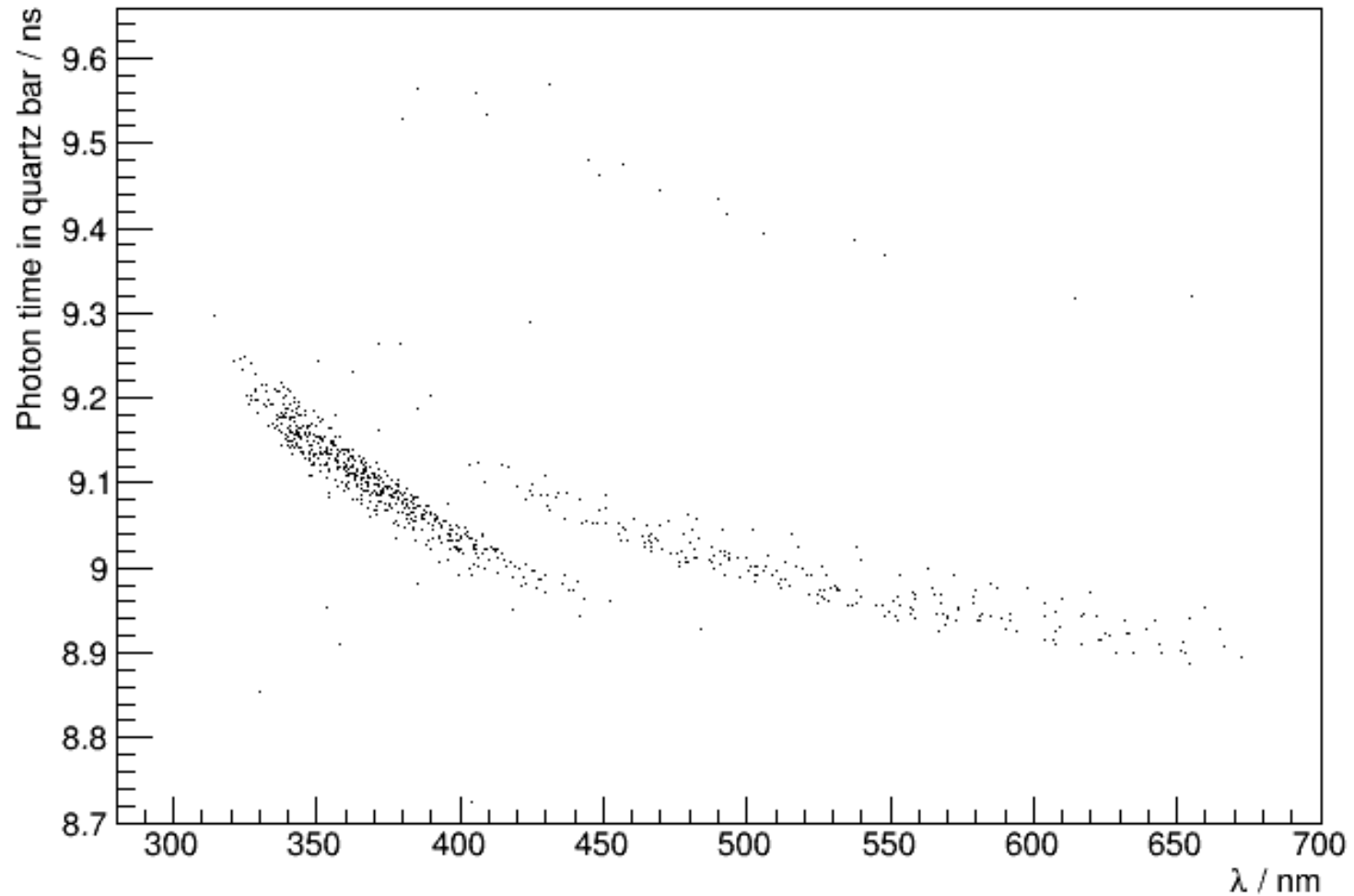
Timing Widths – All Peaks in Ring Images

- All channels were analyzed by peak finding/fitting to extract timing resolutions for all narrow (<1 ns) features in ring image data
- Beam data (black) from experiment 2 (373/512 channels are represented in this figure)
- Monte Carlo (red) has 100 ps electronics contribution as expected from laser results
- Agreement between data and MC is excellent



Impact of Propagation

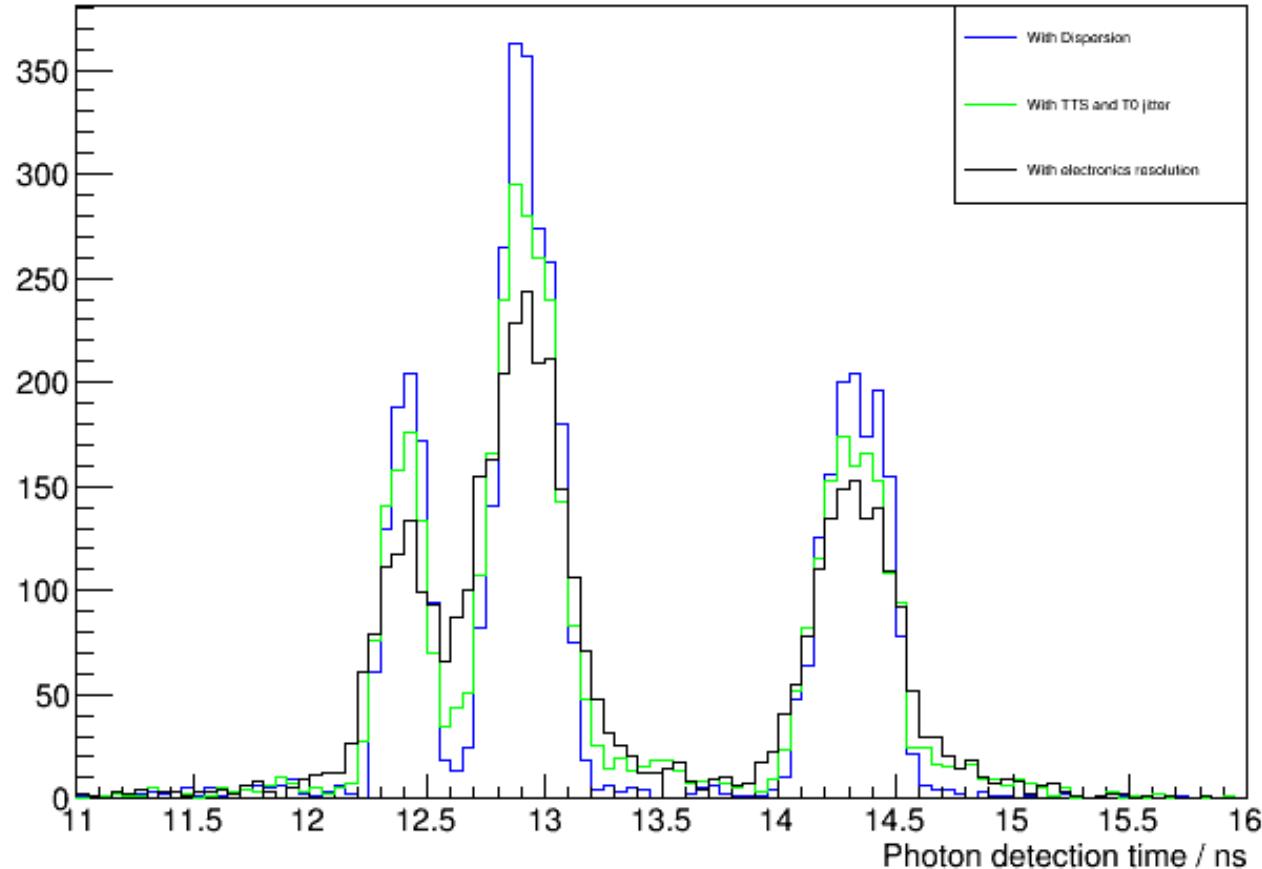
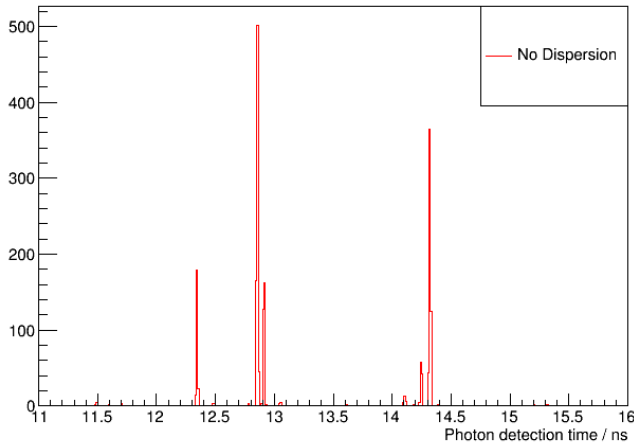
Time in quartz bar vs wavelength for photons hitting PMT 24 ch 1



Narrowest leading edge peaks in MC of beamtest data ($\sim 120\text{ps}$)

Photon detection time for PMT 24 ch 1

Photon detection time for PMT 24 ch 1



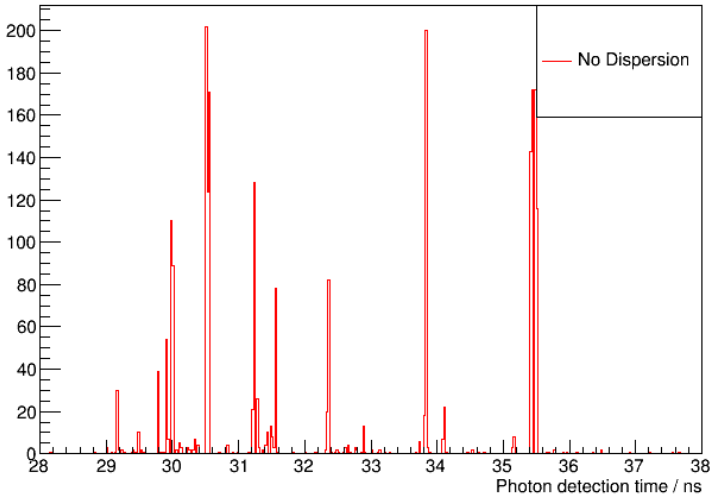
Normal Incidence

1st peak width:

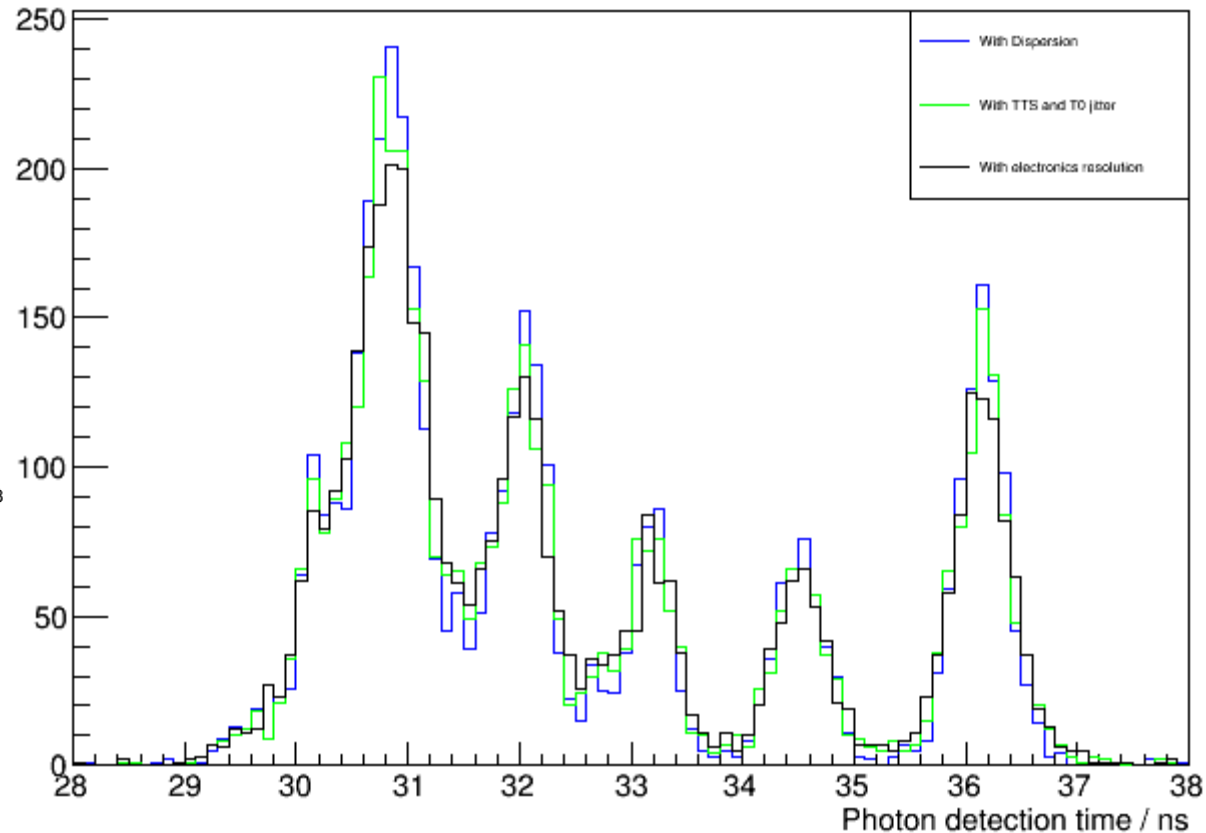
| | |
|------------------|-----------|
| No dispersion: | 6-8ps |
| With dispersion: | 90-100ps |
| +TTS/T0 jitter: | 110-120ps |
| + electronics: | 150-160ps |

Timing for Mirror Reflected Peaks

Photon detection time for PMT 24 ch 1



Photon detection time for PMT 24 ch 1



Mirror peaks:

No dispersion: 6-8ps

With dispersion: 300-350ps

+TTS/T0 jitter: 300-350ps as above plus 0-10ps

+ electronics: 300-350ps as above plus 10-20ps

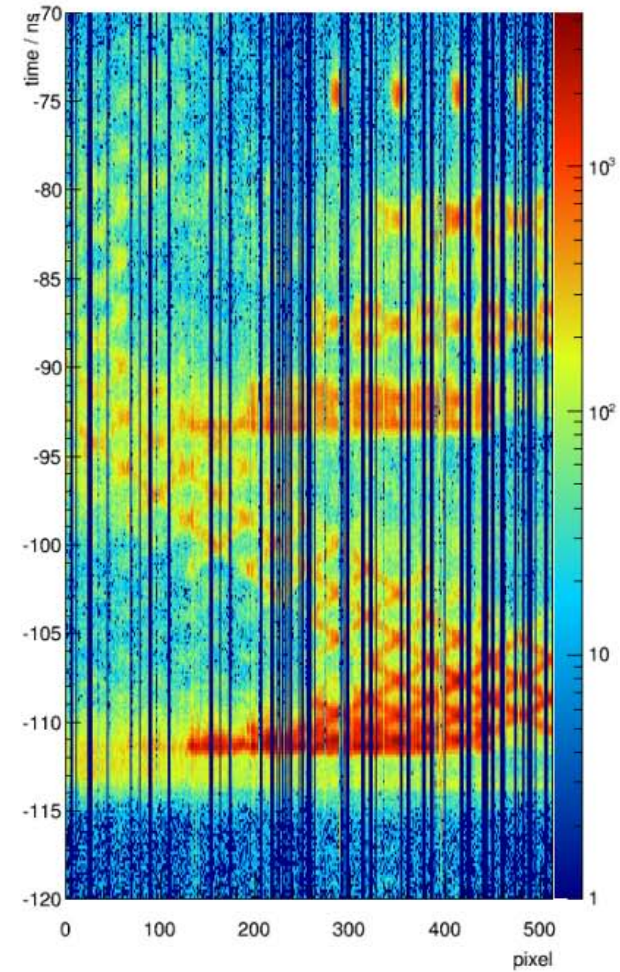
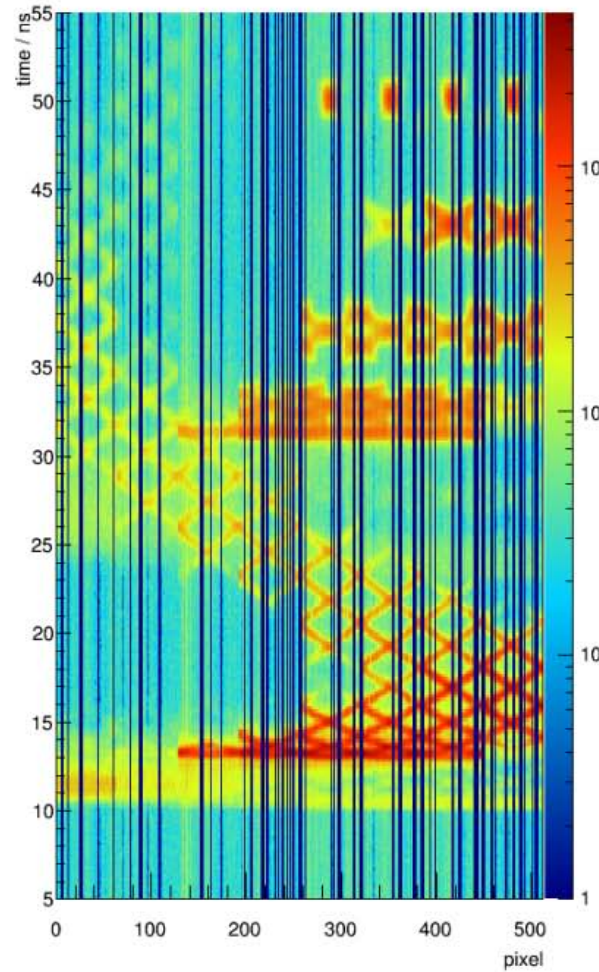
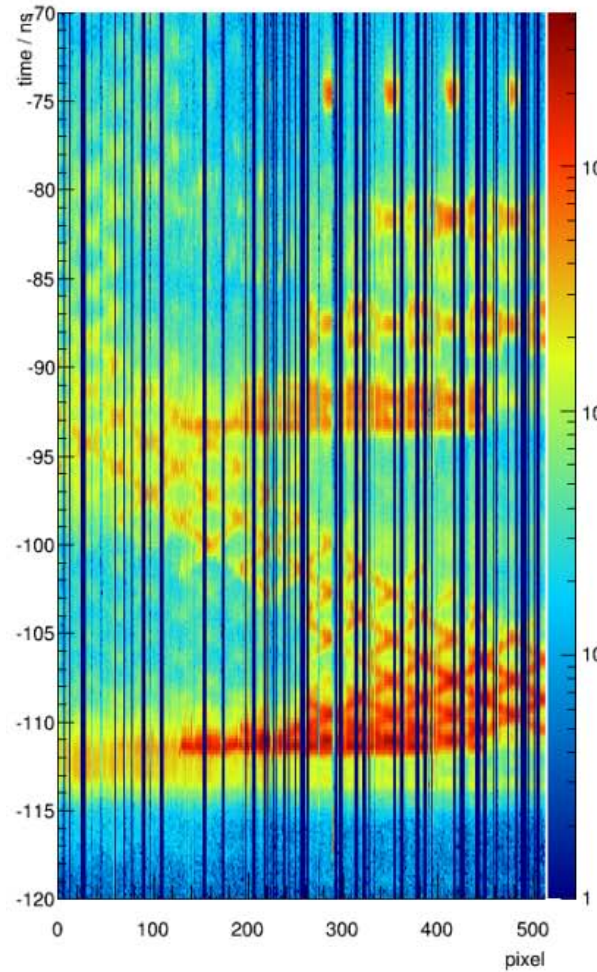
Data/MC Ring Images

Normal Incidence

Data ring image for $\cos\theta = 0.00$

Simulated ring image for $\cos\theta = 0.00$

Data ring image (with LEPS TOF cut) for $\cos\theta = 0.00$

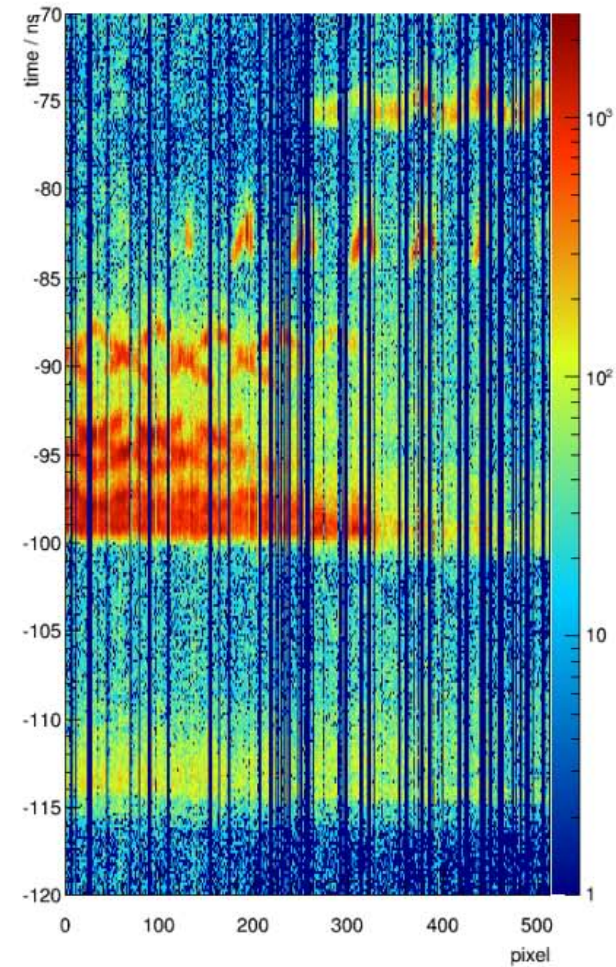
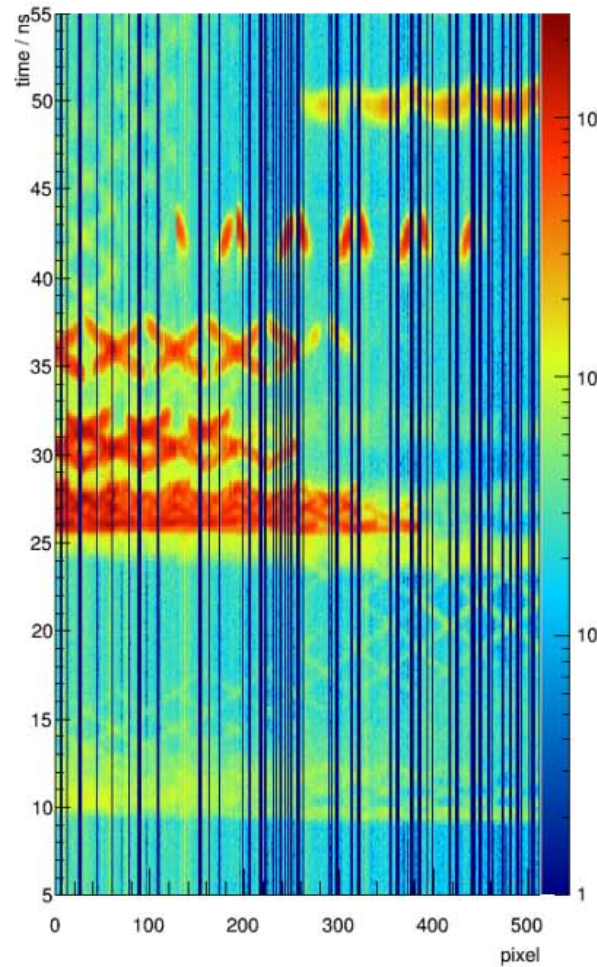
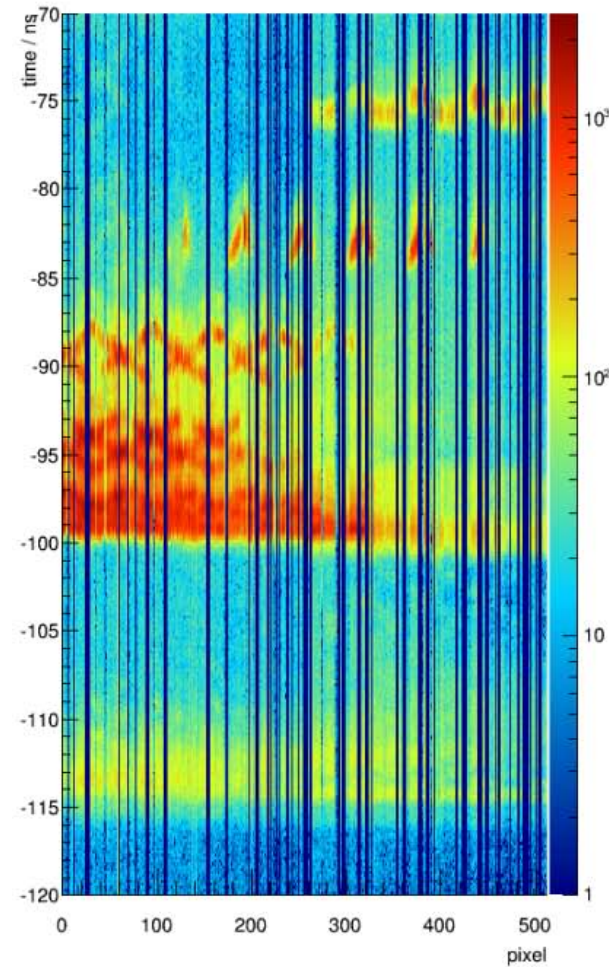


Data/MC Ring Images Inclined Angle

Data ring image for $\cos\theta = 0.43$

Simulated ring image for $\cos\theta = 0.43$

Data ring image (with LEPS TOF cut) for $\cos\theta = 0.43$

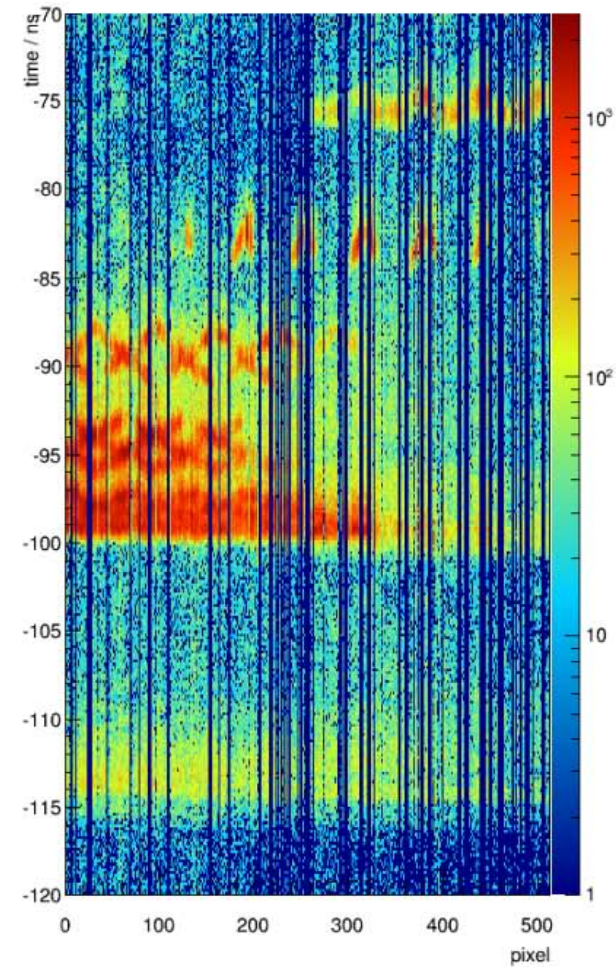
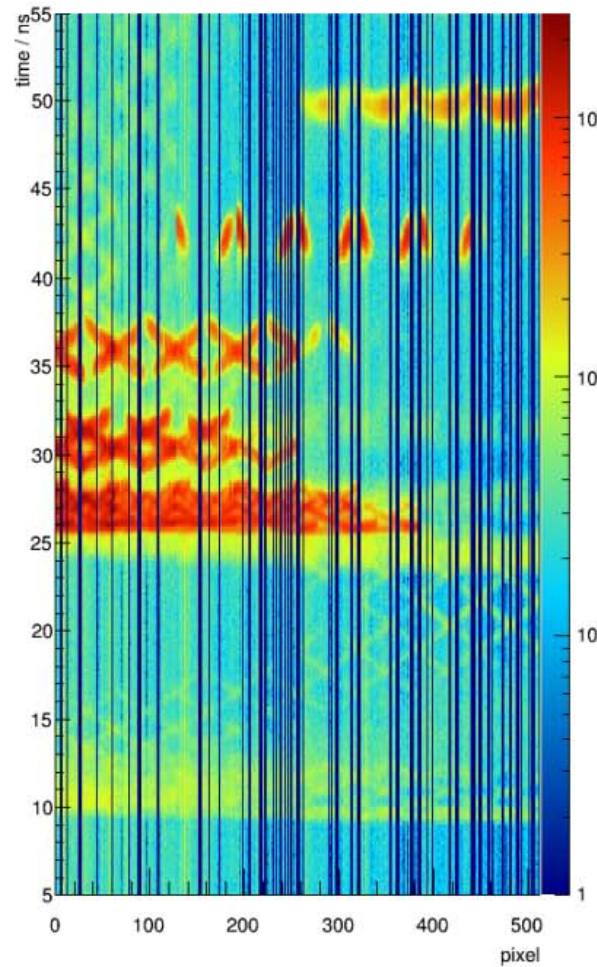
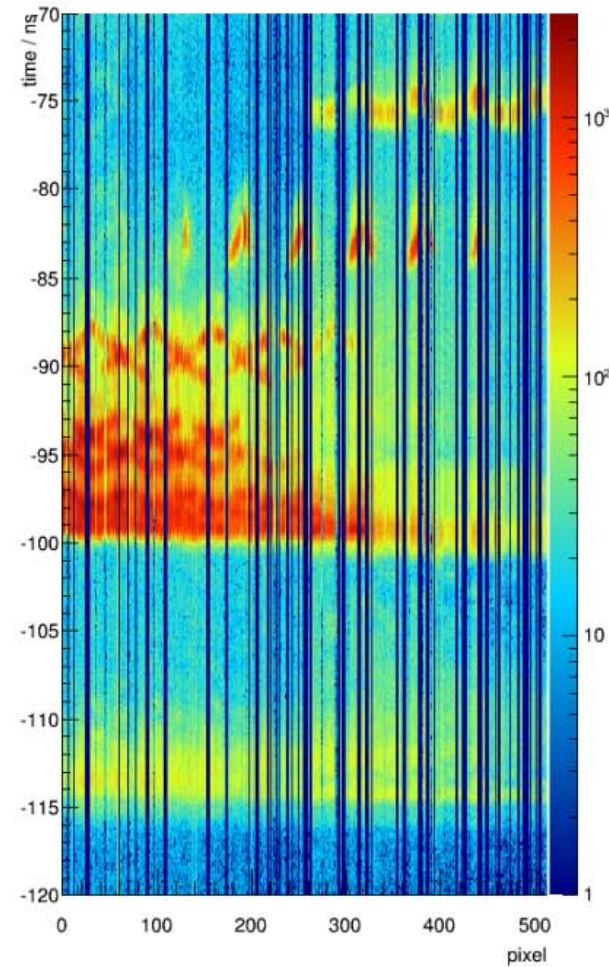


Data/MC Ring Images Near Detector Edge

Data ring image for $\cos\theta = 0.43$

Simulated ring image for $\cos\theta = 0.43$

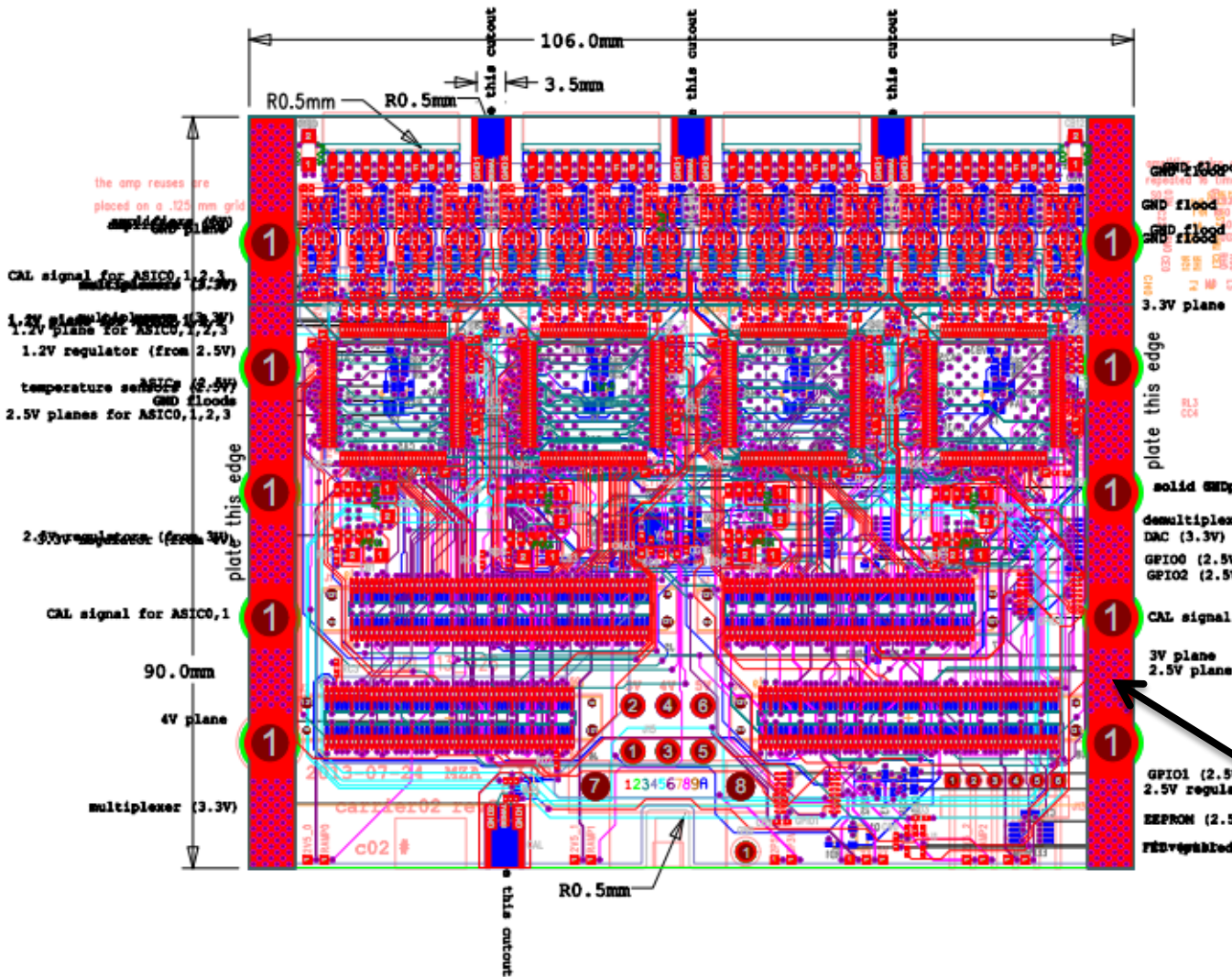
Data ring image (with LEPS TOF cut) for $\cos\theta = 0.43$



Improvements to carrier02

- ✓ Will populate with improved amplifiers
 - ✓ add series resistor and capacitors to V_{adjN}/V_{adjP} (10 Ohm+200pF+47nF+2uF)
 - ✓ exchange SMA connectors for MMCX
 - ✓ exchange 12 bit external DAC for 16 bit one in same series
 - ✓ re-visit c02 wiring to allow powering entire boardstack with just one cable
 - ✓ extend width of boards and add holes for new thermal wall structure concept
 - ✓ swap ASIC regulator for one with a shutdown feature
- full list at <http://www.phys.hawaii.edu/~mza/PCB/iTOP/boardstack-v3.html>

Layout of carrier02 revC



| layer stackup | | |
|---------------|--------|-------------------------|
| dielectric | copper | layer # / description |
| | 1 oz | 1 top routing |
| 9 mils | 1 oz | 2 GND |
| 3.15 mils | 1 oz | 3 horizontal-routing |
| 3.15 mils | 1 oz | 4 2.5V 3.3V 4V |
| 8 mils | 1 oz | 5 1.25V 2.5V 3V GND CAL |
| 8 mils | 1 oz | 6 routing |
| 8 mils | 1 oz | 7 5V |
| 3.15 mils | 1 oz | 8 vertical-routing |
| 3.15 mils | 1 oz | 9 GND |
| 9 mils | 1 oz | 10 bottom routing |

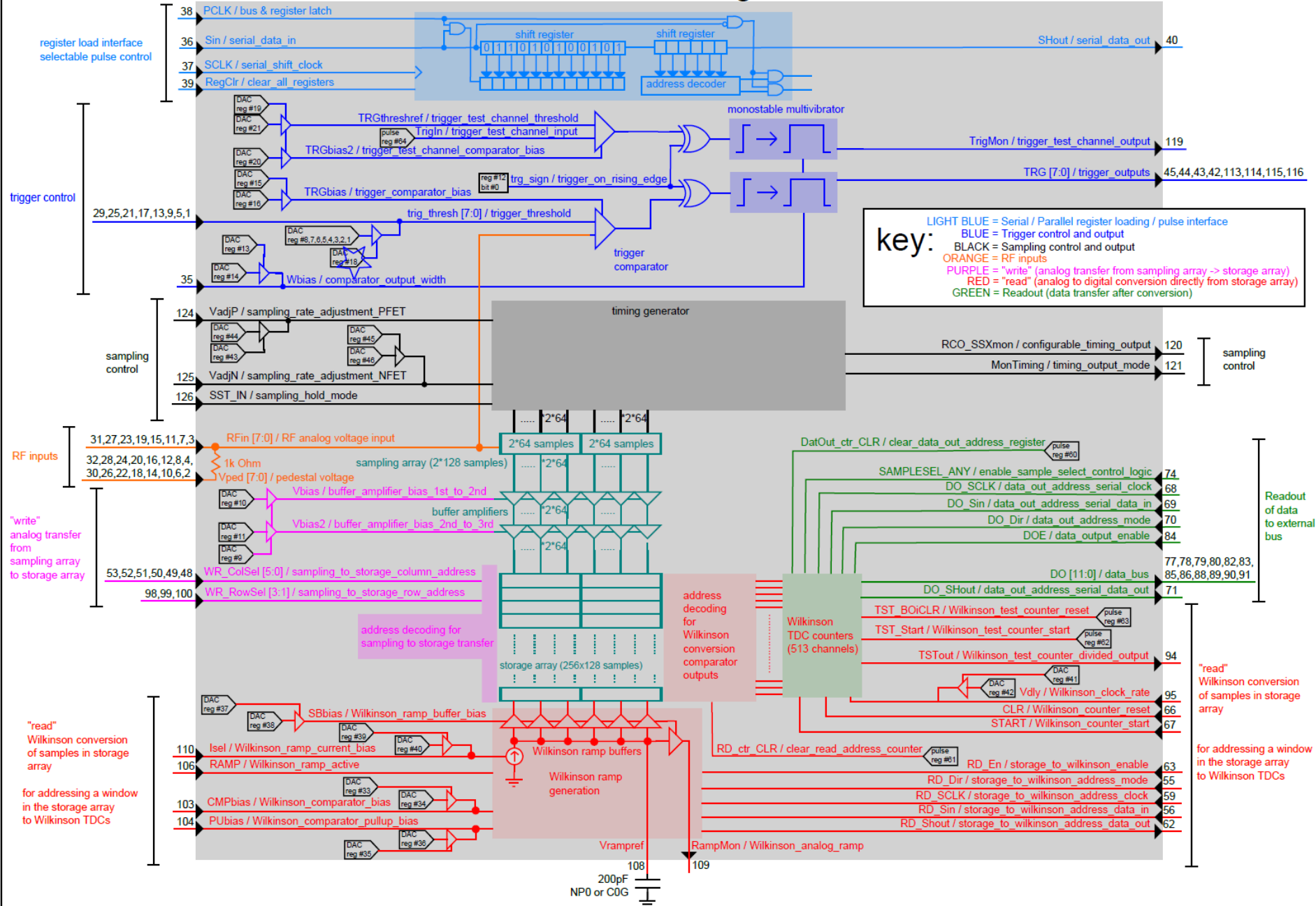
plated edges: left and right
 silkscreen color = white
 soldermask color = red
 plating = ENIG
 overall thickness = 68.6 mils
 overall board dimensions = 106 mm * 90 mm

Improved –
 pin-tie
 thermal
 stack

design posted at:

<http://www.phys.hawaii.edu/~mza/PCB/iTOP/carriers/index.html>

IRS3B block diagram

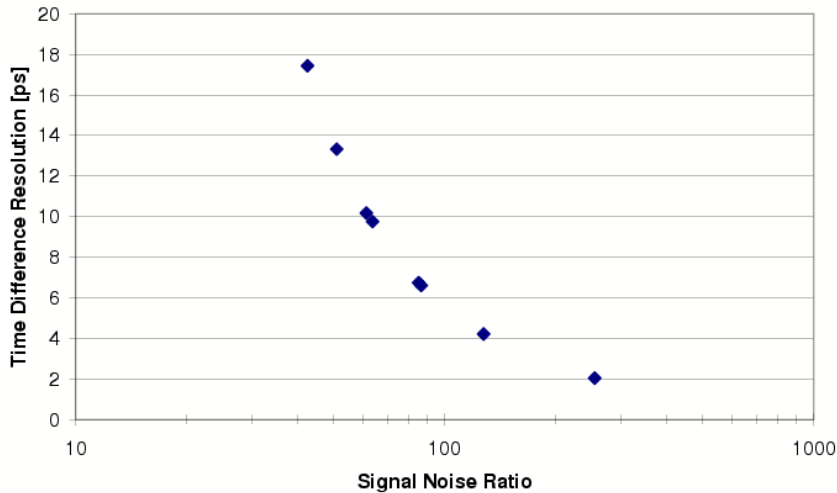


Expectations – matched to measurements

- Noise/amplitude
- Non-linearity
- Timebase non-uniformity

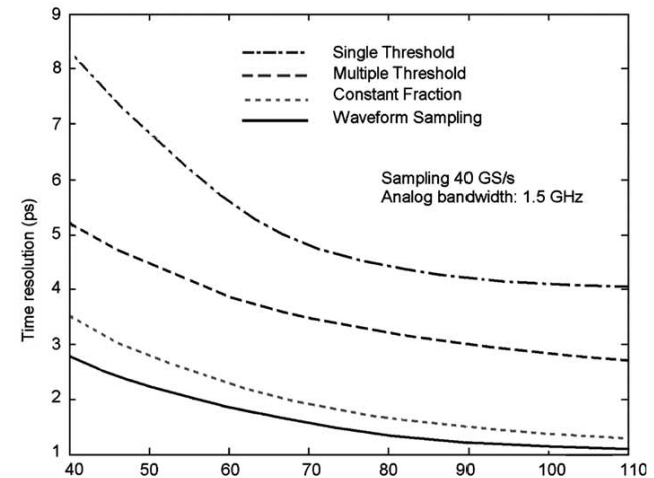
1GHz analog bandwidth, 5GSa/s

Time Difference Dependence on Signal-Noise Ratio (SNR)



G. Varner and L. Ruckman
NIM A602 (2009) 438-445.

Simulation includes MCP response



J-F Genat, G. Varner, F. Tang, H. Frisch
NIM A607 (2009) 387-393.

